

Keynote

pcim  
EUROPE ...*digital*  
*days*



# Next-Generation SiC/GaN Three-Phase Variable-Speed Drive Inverter Concepts

Johann W. Kolar & Jonas E. Huber

## Outline

- ▶ *Introduction to VSDs*
- ▶ *SiC Sinus-Inverter*
- ▶ *GaN Multi-Level Inverter*
- ▶ *SiC Buck-Boost Inverter*
- ▶ *I-DC Link Inverter & GaN AC-Switches*
- ▶ *Conclusions*

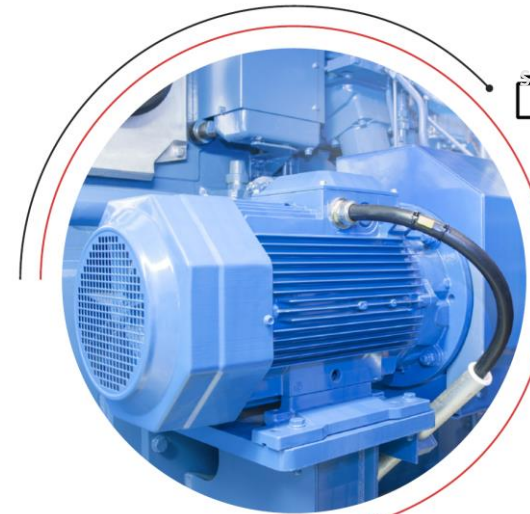
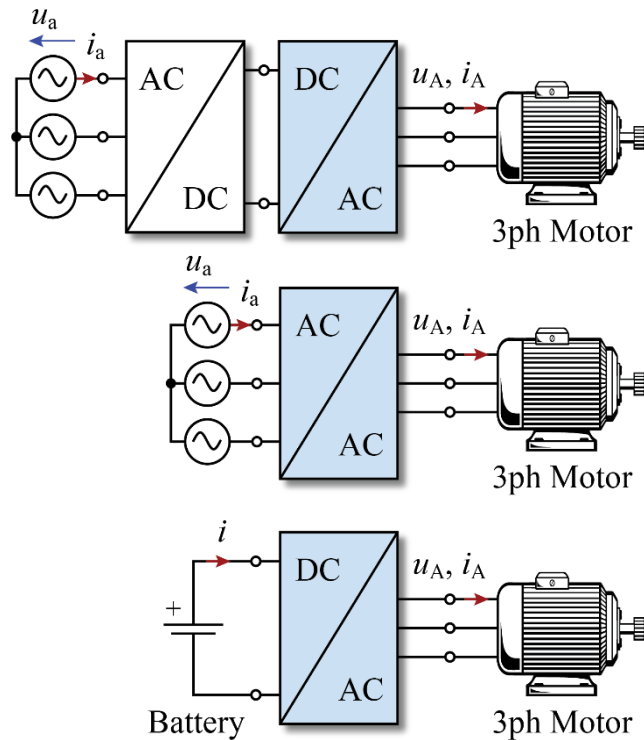


M. Antivachis  
J. Azurza  
D. Bortis  
M. Guacci  
M. Haider  
F. Krismer  
S. Miric  
J. Miniböck  
N. Nain  
P. Niklaus  
G. Rohner  
F. Vollmaier  
D. Zhang  
G. Zulauf

Acknowledgement

# Variable Speed Drive Concepts

- **DC-Link Based AC/DC/AC OR Matrix-Type AC/AC Converters**
- **Battery OR Fuel-Cell Supply OR Common DC-Bus Concepts**



**38%**  
of electric energy use is for motors  
in commercial buildings.

Source: **ABB**

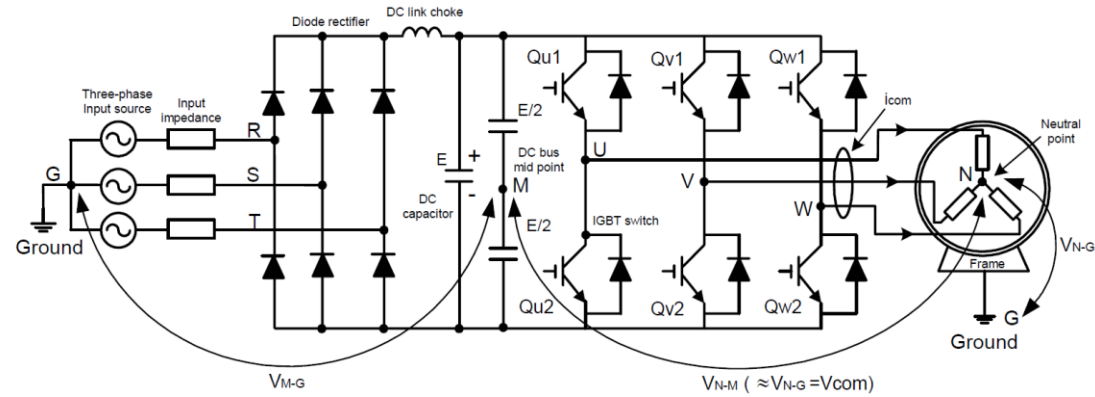


**70%**  
of electricity consumed by industry  
is used in electric motor systems.

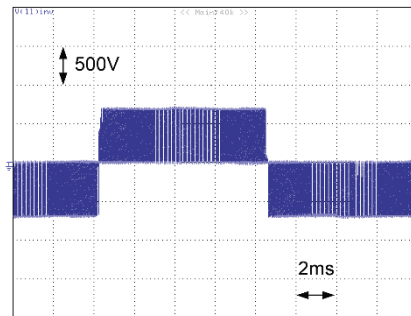
- **45% of World's Electricity Used for Motors in Buildings & Industrial Applications**

# State-of-the-Art Drive System

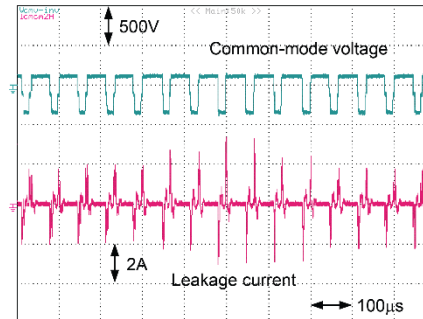
- **Standard 2-Level Inverter** — Large Motor Inductance / Low Sw. Frequency
- **Shielded Motor Cables / Limited Cable Length / Insulated Bearings / Acoustic Noise**



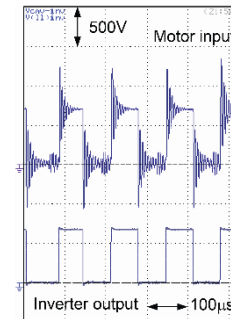
Source: YASKAWA



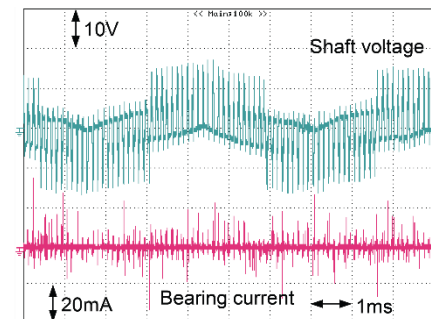
• **Line-to-Line Voltage**



| **CM Leakage Current**



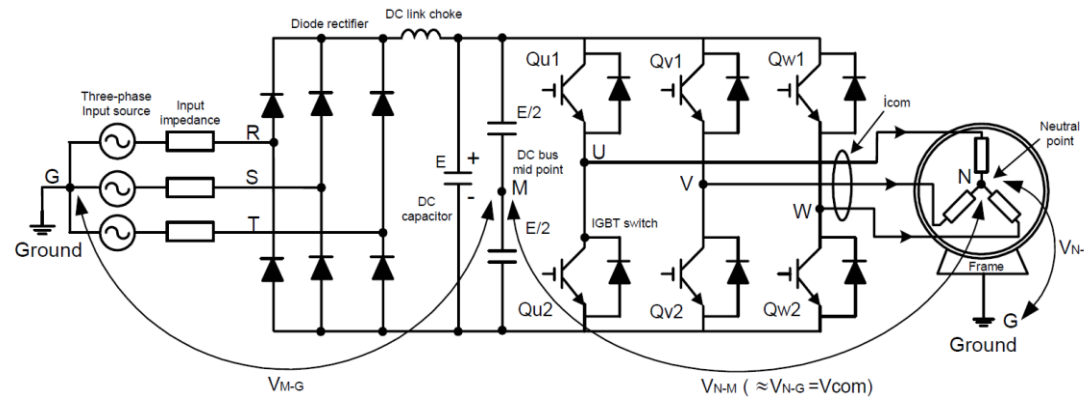
| **Motor Surge Voltage**



| **Bearing Current**

# State-of-the-Art Drive System

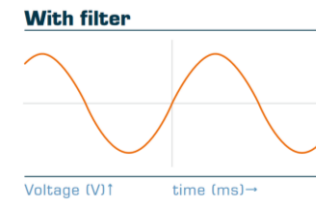
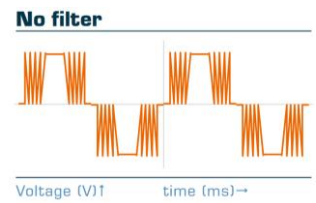
- Measures Ensuring EMI Compliance / Longevity of Motor Insulation & Bearings
- Motor Reactor | *dv/dt Filters* | *DM-Sinus Filters* | *Full-Sinus Filters* | *Multi-Level Inverters*



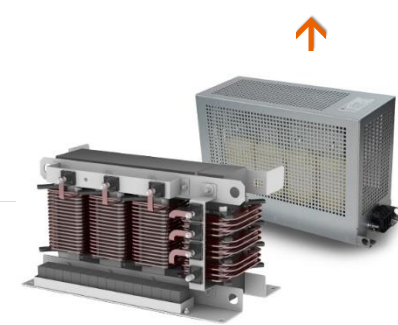
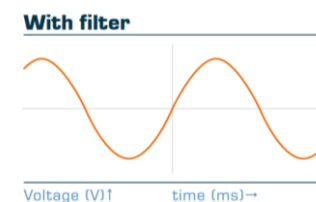
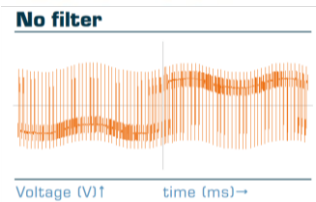
Source: YASKAWA

Source: BLOCK

MOTOR VOLTAGE PHASE-PHASE



MOTOR VOLTAGE PHASE-GROUND



- Small Filter Size → High Sw. Freq. → SiC | GaN

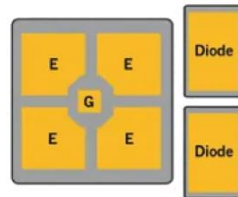
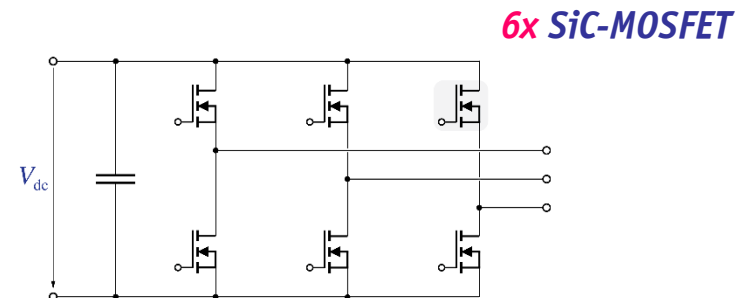
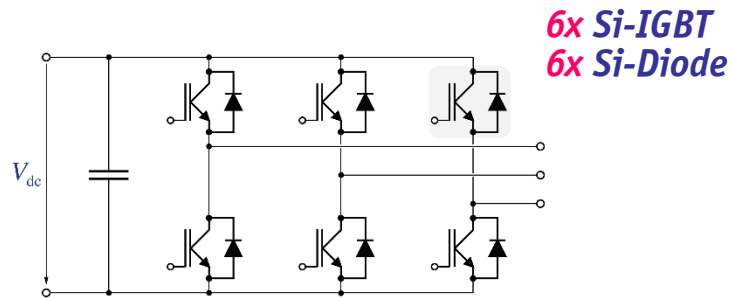


Source: [www.clipart-library.com](http://www.clipart-library.com)

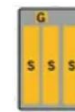
**SiC | GaN**

# Si vs. SiC

- **Si-IGBT / Diode** → Const. On-State Voltage, Turn-Off Tail Current & Diode Reverse Recovery Current
- **SiC-MOSFET** → Loss Reduction @ Part Load BUT Higher  $R_{th}$



Source: ATZ elektronik



1200V 100A  
Die Size: **98.8mm<sup>2</sup> + 39.4mm<sup>2</sup>**

Source: Infineon

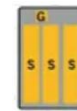
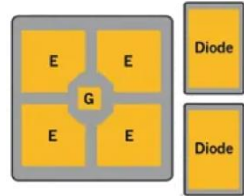
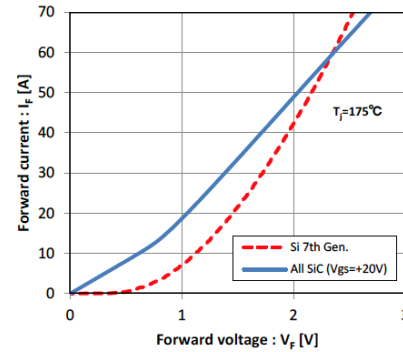
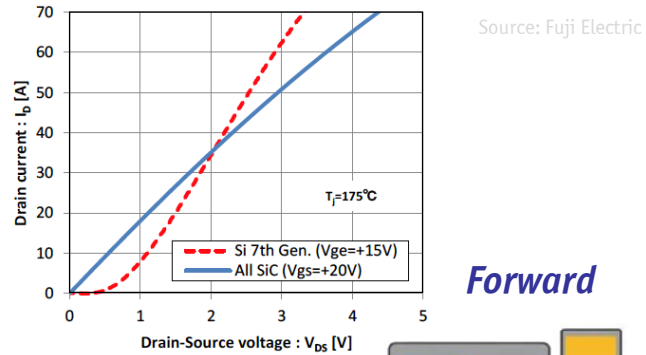
1200V 100A  
Die Size: **25.6mm<sup>2</sup>**

Source: Cree

- Space Saving of **>30%** on Module Level (!)
- Extremely High  $dv/dt$  → Motor Insul. Stress / Reflections / Bearing Curr. / EMI

# Si vs. SiC

- **Si-IGBT / Diode** → **Const. On-State Voltage, Turn-Off Tail Current & Diode Reverse Recovery Current**
- **SiC-MOSFET** → **Loss Reduction @ Part Load BUT Higher  $R_{th}$**



**1200V 100A**  
**Die Size: 98.8mm<sup>2</sup> + 39.4mm<sup>2</sup>**

**1200V 100A**  
**Die Size: 25.6mm<sup>2</sup>**

Source: Infineon

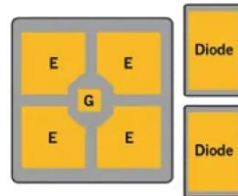
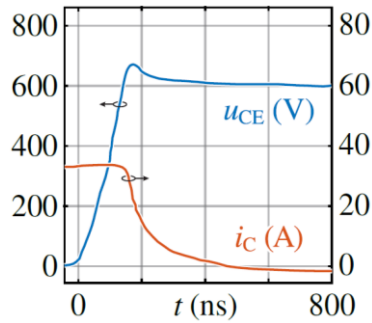
Source: Cree

- **Space Saving of >30% on Module Level (!)**
- **Extremely High dv/dt** → **Motor Insul. Stress / Reflections / Bearing Curr. / EMI**



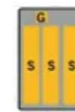
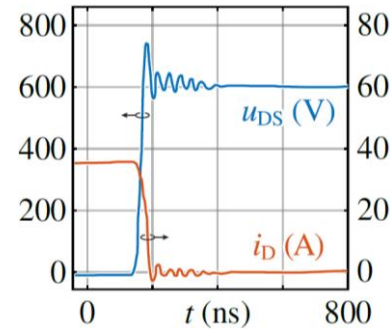
# Si vs. SiC

- **Si-IGBT / Diode** → **Const. On-State Voltage, Turn-Off Tail Current & Diode Reverse Recovery Current**
- **SiC-MOSFET** → **Loss Reduction @ Part Load BUT Higher  $R_{th}$**



1200V 100A  
Die Size: **98.8mm<sup>2</sup> + 39.4mm<sup>2</sup>**

Source: Infineon



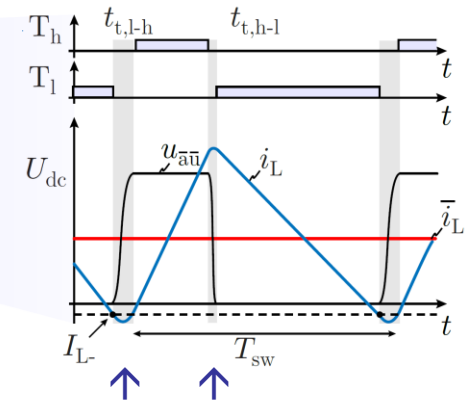
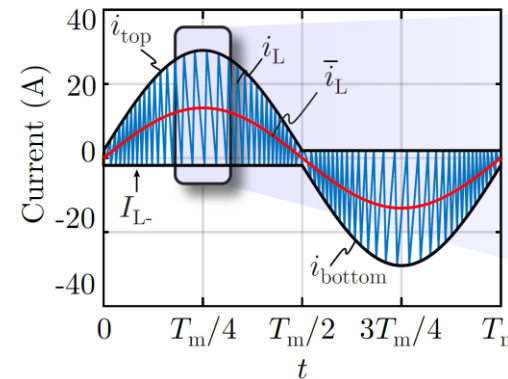
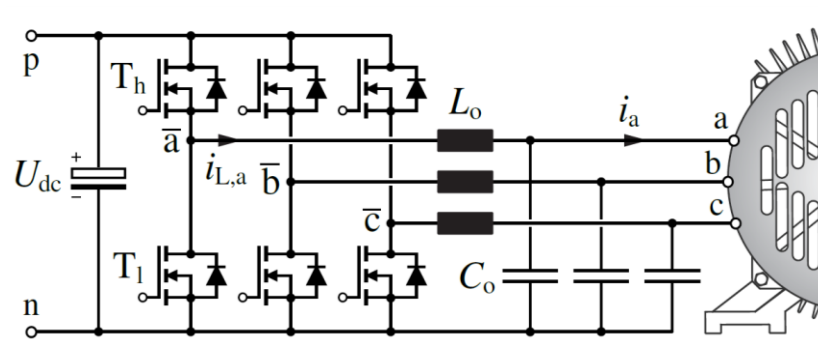
1200V 100A  
Die Size: **25.6mm<sup>2</sup>**

Source: Cree

- **Space Saving of >30% on Module Level (!)**
- **Extremely High dv/dt** → **Motor Insul. Stress / Reflections / Bearing Curr. / EMI**

# Full-Sinewave Filter & ZVS Operation

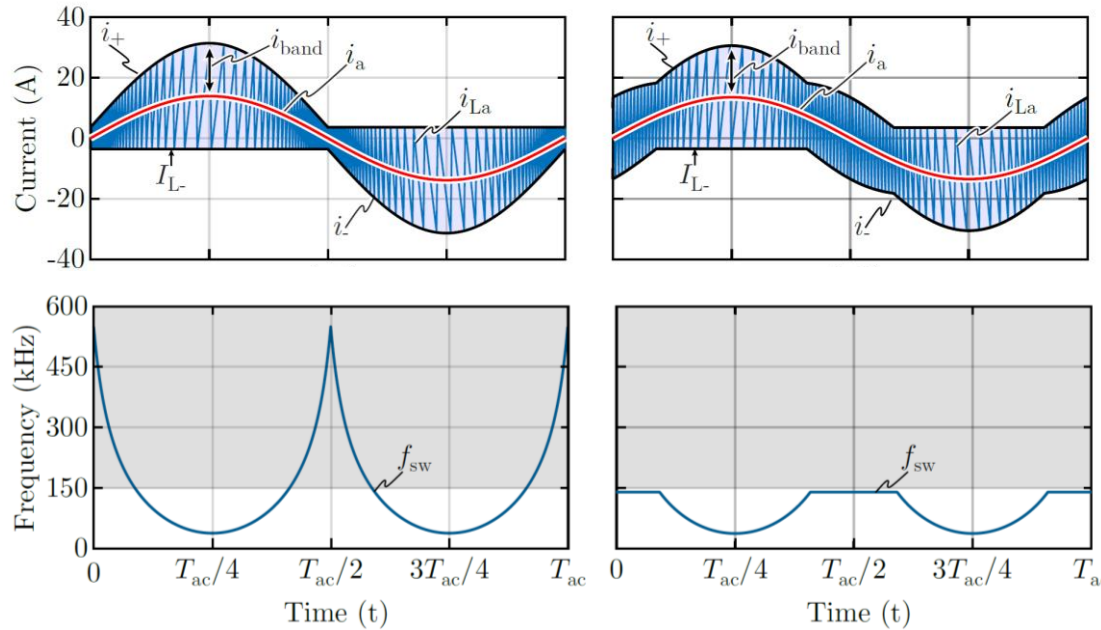
- **Sinusoidal Output Voltage**
- **Triangular Current Mode (TCM)** → **ZVS of Inv. Bridge-Legs**
- **High Sw. Frequency & TCM** → **Low Filter Inductor Volume**



- **Only 33% Increase of Transistor Conduction Losses Compared to CCM (!)**
- **Very Wide Switching Frequency Variation**

# Frequency-Bounded TCM — B-TCM

- *Very Wide Sw. Frequency Variation of Conventional TCM*
- *Allow Larger Current Ripple Around Zero Crossings*



★ *99.7% Semicond. Eff.  
99.5% Total Efficiency*

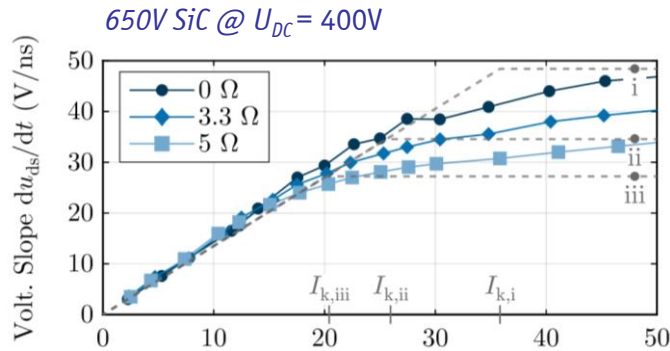
*B-TCM Bridge-Leg  
1200V SiC MOSFETs*

*P = 2.2kW  
U<sub>DC</sub> = 800V  
f<sub>s</sub> = 50kHz...140kHz  
L = 52uH (106 cm<sup>3</sup>)  
C = 8.8uF*

- *TCM → B-TCM — 10% Further Increase of Transistor Conduction Losses*

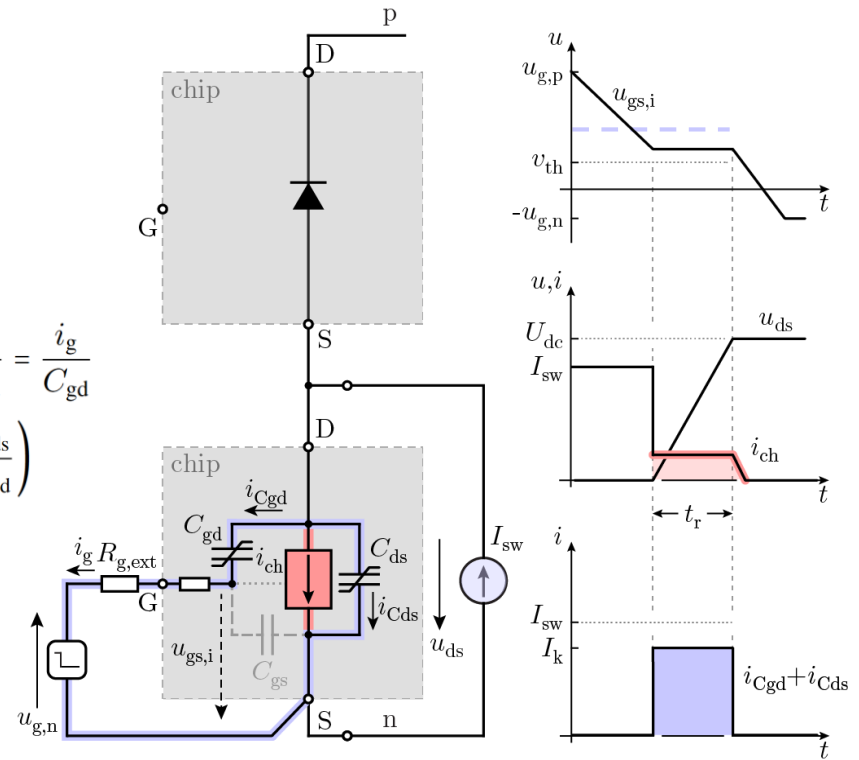
# Remark Residual ZVS Losses

- Overlap of  $u_{DS}$  & Channel Current  $i_{ch}$  @ High  $I_{sw} > I_k$
- Temporary Turn-on Due to  $u_{GS,i} > u_{th}$



$$\frac{du_{ds}}{dt} \Big|_{\max} = \frac{I_k}{C_{ds} + C_{gd}} = \frac{i_g}{C_{gd}}$$

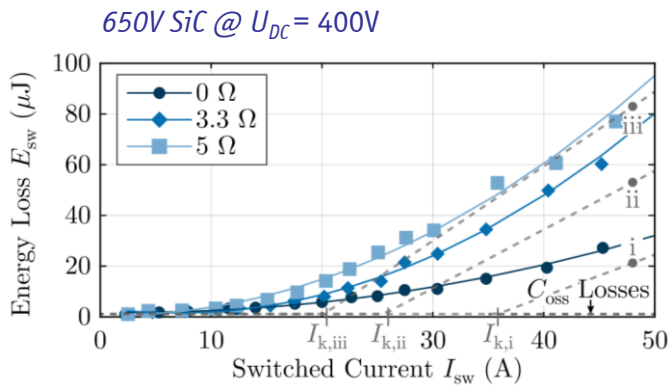
$$I_k = \frac{u_{th} + u_{g,n}}{R_g} \left( 1 + \frac{C_{ds}}{C_{gd}} \right)$$



- “Kink” Current  $I_k$  Dependent on Inner & Outer Gate Resistance &  $u_{g,n}$

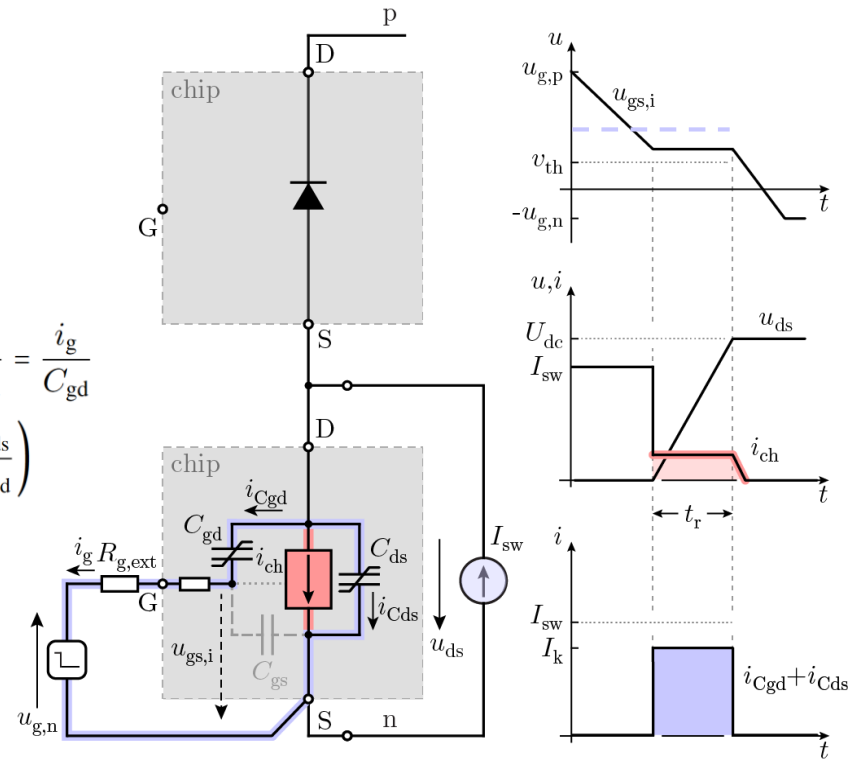
# Remark Residual ZVS Losses

- Overlap of  $u_{DS}$  & Channel Current  $i_{ch}$  @ High  $I_{sw} > I_k$
- Temporary Turn-on Due to  $u_{GS,i} > u_{th}$



$$\left. \frac{du_{ds}}{dt} \right|_{\max} = \frac{I_k}{C_{ds} + C_{gd}} = \frac{i_g}{C_{gd}}$$

$$I_k = \frac{u_{th} + u_{g,n}}{R_g} \left( 1 + \frac{C_{ds}}{C_{gd}} \right)$$

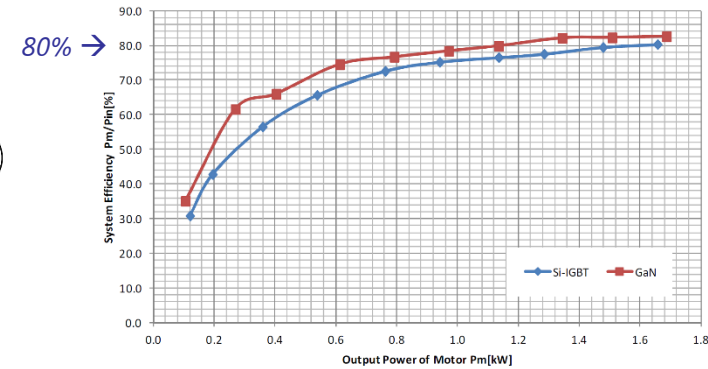
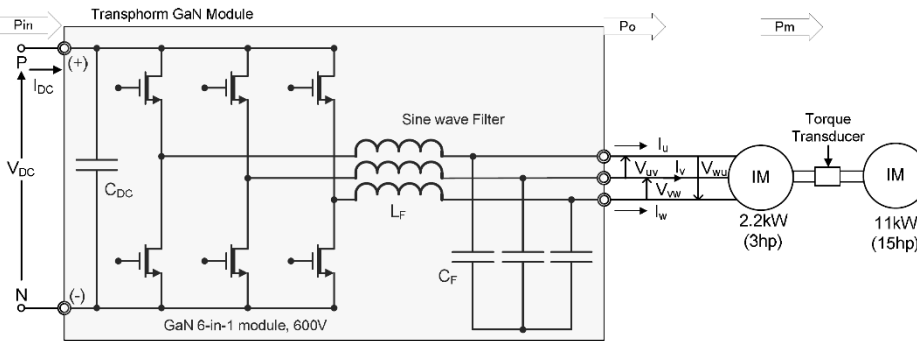
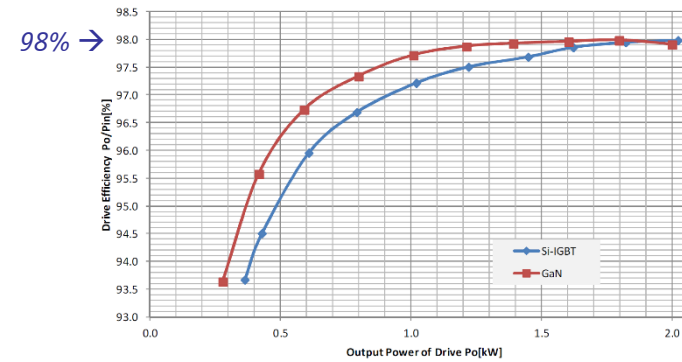
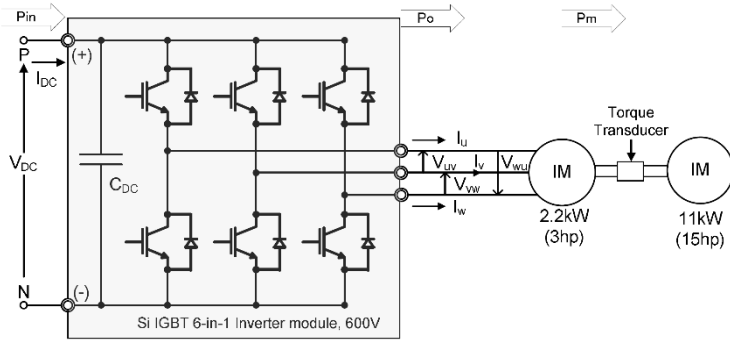


- "Kink" Current  $I_k$  Dependent on Inner & Outer Gate Resistance &  $u_{g,n}$

# Si IGBT vs. GaN Inverter System

Source: **YASKAWA**

- Comparison of **GaN Inverter with LC-Filter ( $f_s=100\text{kHz}$ )** to **Si-IGBT System (No Filter,  $f_s=15\text{kHz}$ )**
- Measurement of **Inverter Stage & Overall Drive Losses @ 60Hz**



→ **2% Higher Efficiency of GaN System Despite LC-Filter (Saving in Motor Losses) !**



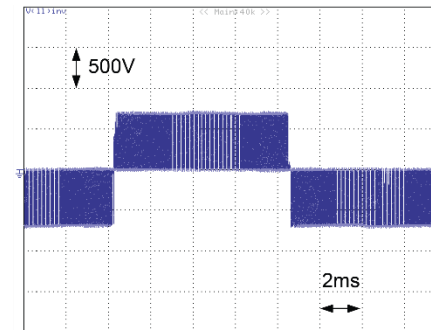
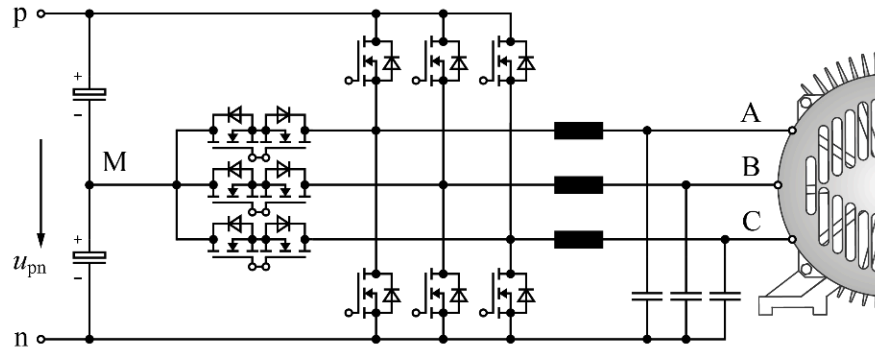


Source: [www.clipart-library.com](http://www.clipart-library.com)

## *Multi-Level Inverter*

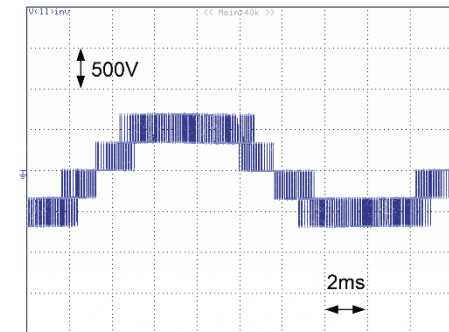
# 3-Level Inverter Concepts

- Higher Number of Output Voltage Levels / Lower CM Voltage Steps
- Neutral Point Clamped | Flying Capacitor | T-Type Bridge-Leg Topologies



2-Level Bridge-Leg

## Line-to-Line Voltage



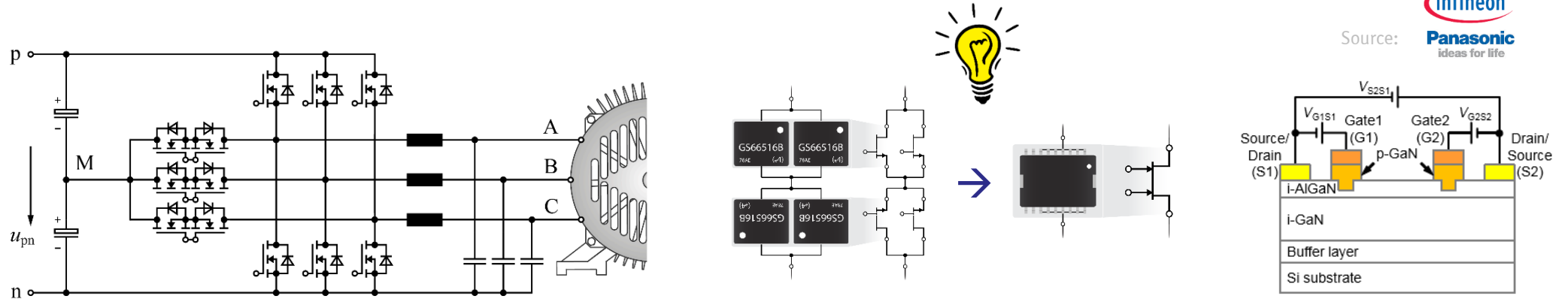
3-Level Bridge-Leg

- Complicated Bridge-Leg Structure
- On-State-Losses of Series-Connected Switches



# 3-Level T-Type Inverter

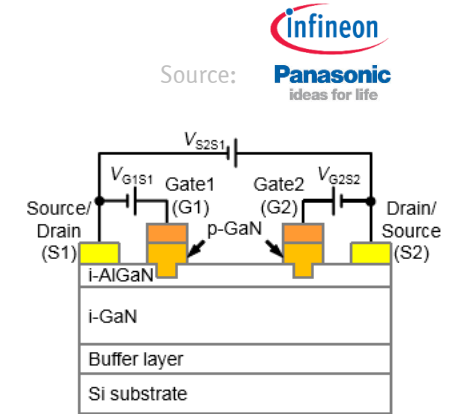
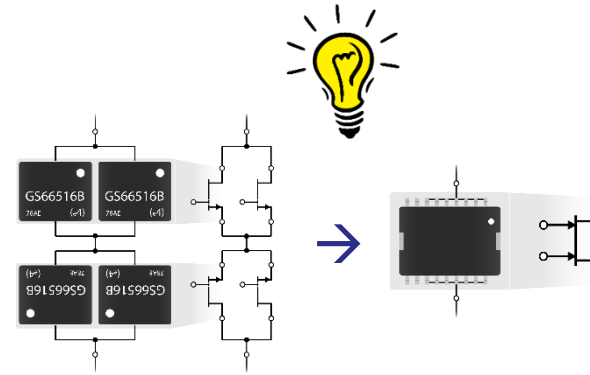
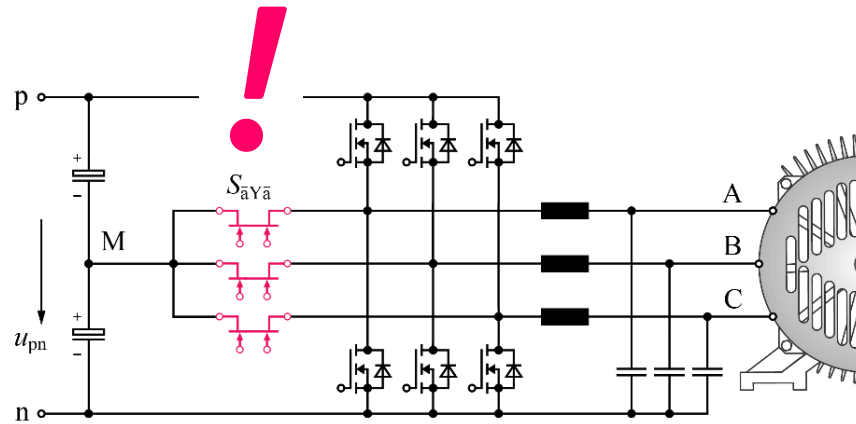
- Utilization of 600V Monolithic Bidirectional GaN Switches
- 2-Gate Structure Provides Full Controllability



- Factor 4 (!) Reduction of Chip Area vs. Discrete Realization

# 3-Level T-Type Inverter

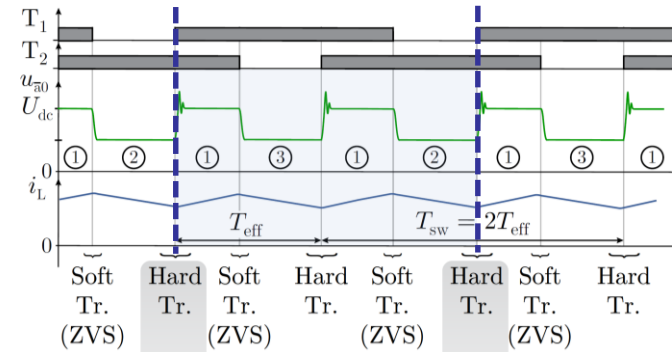
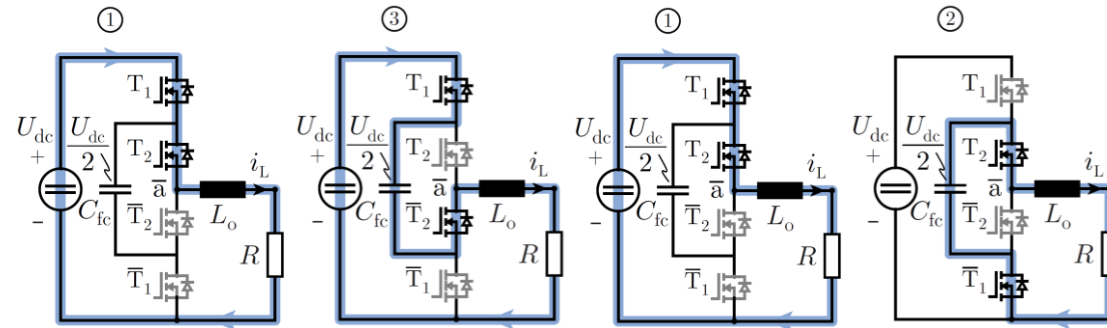
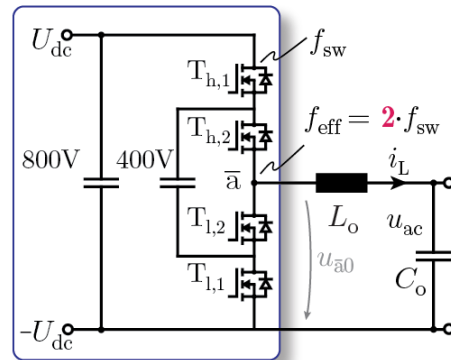
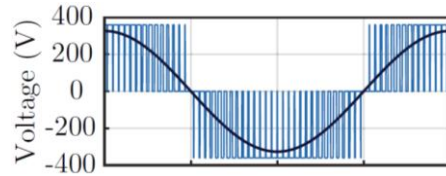
- Utilization of **600V Monolithic Bidirectional GaN Switches**
- **2-Gate Structure Provides Full Controllability**



- **Factor 4 (!) Reduction of Chip Area vs. Discrete Realization**

# Flying Cap. (FC) 3-Level Converter

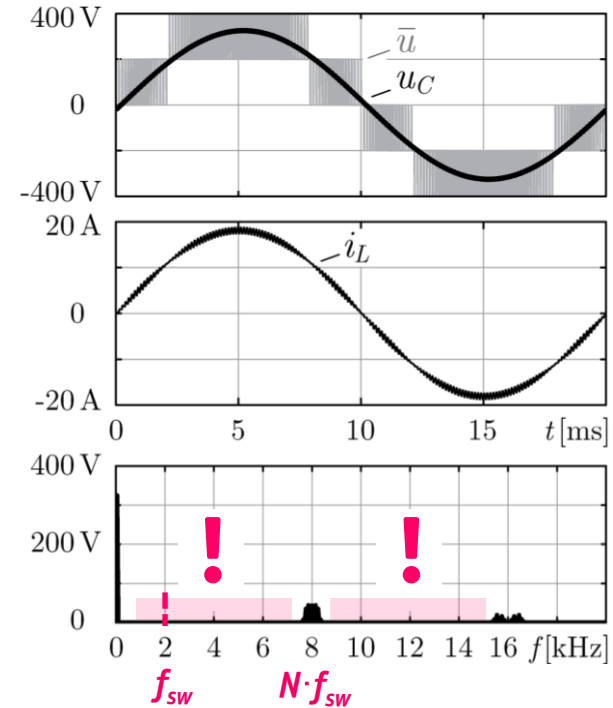
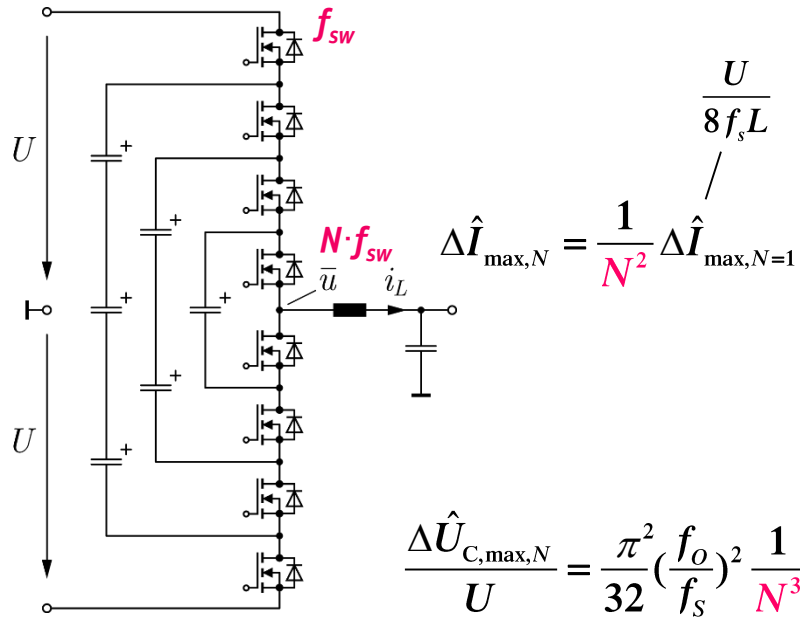
- 3-Level Flying Cap. (FC) Converter → No Connection to DC-Midpoint
- Involves All Switches in Voltage Generation → Eff. Doubles Device Sw. Frequency



- FC Voltage Balancing Possible also for DC Output

# Scaling of Flying Cap. Multi-Level Concepts

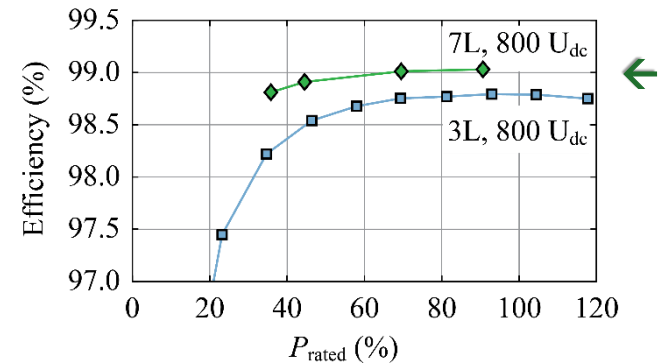
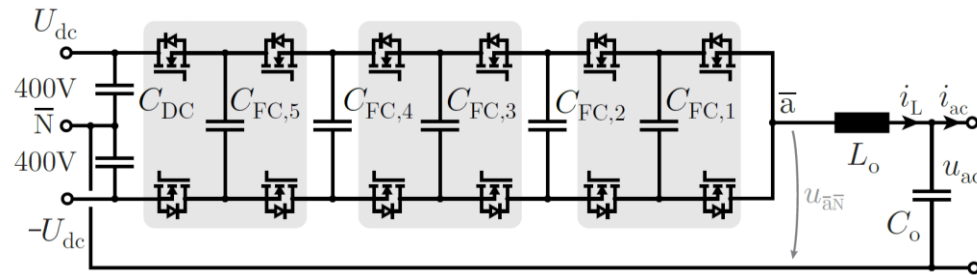
- **Series Interleaving** → **Reduced Ripple**
- $f_{sw,eff} = N \cdot f_{sw}$  @  $f_{sw}$ -Determined (!) **Switching Losses**
- **Lower Overall On-Resistance** @ Given Blocking Voltage
- **Application of LV Technology to HV**



- **Scalability / Manufacturability / Standardization / Redundancy**

# 7-Level Flying Cap. 200V GaN Inverter

- **DC-Link Voltage** 800V
- **Rated Power** 2.2 kW / Phase
- **99% Efficiency** → **Natural Convection Cooling (!)**

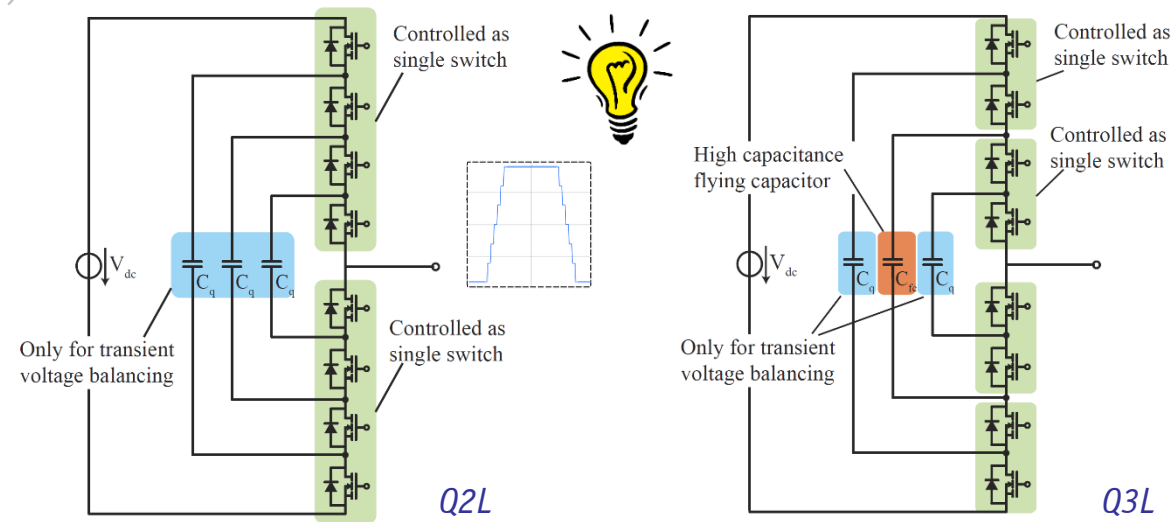


- **High Effective Sw. Frequency** ( $6 \times 30\text{kHz} = 180\text{kHz}$ ) → **Small Filter Inductor  $L_o$**

# Quasi-2L & Quasi-3L Flying Cap. Inverters

- Operation of N-Level Topology in 2-Level or 3-Level Mode
- Intermediate Voltage Levels Only Used During Sw. Transients

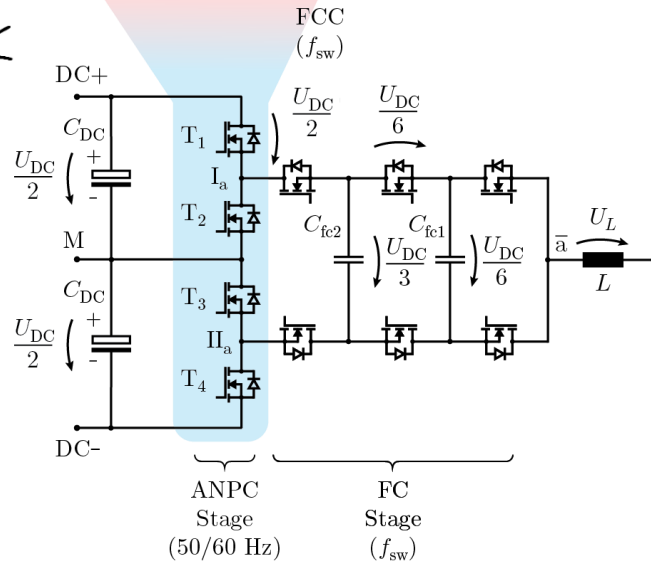
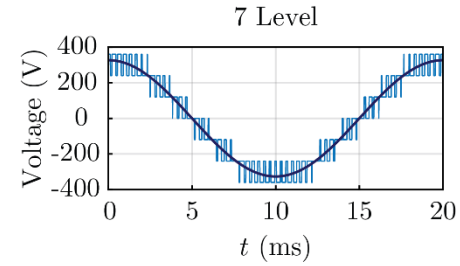
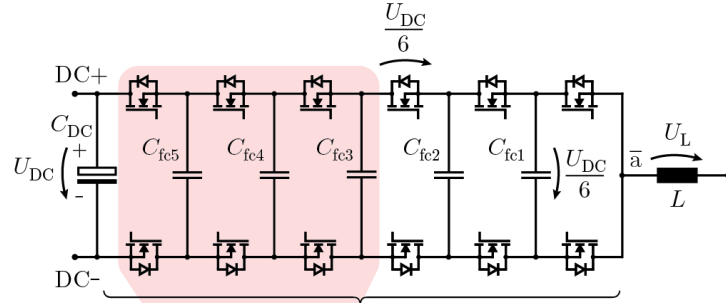
- Schweizer (2017)



- Clear Partitioning of Overall Blocking Voltage & Small Flying Capacitors
- Low Voltage/Low  $R_{DS(on)}$ /Low \$ MOSFETs → High Efficiency / No Heatsinks / SMD Packages

# 3-Φ Hybrid 7-Level Inverter

- Realization of a **99%+ Efficient 10kW 3-Φ 400V<sub>rms,LL</sub> Inverter System**
- **7-Level Hybrid Active NPC Topology / LV Si-Technology**



**99.35%**  
**2.6kW/kg**  
**56 W/in<sup>3</sup>**

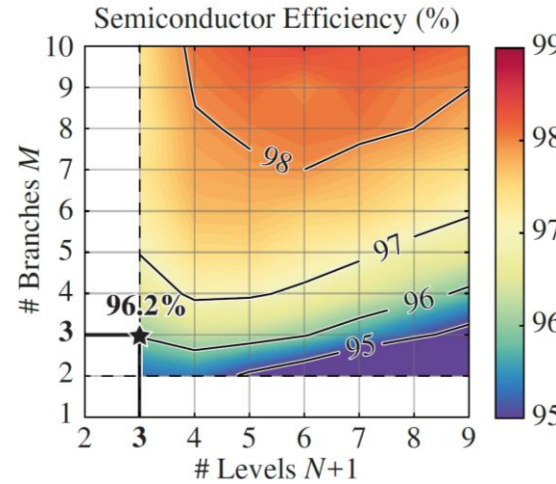
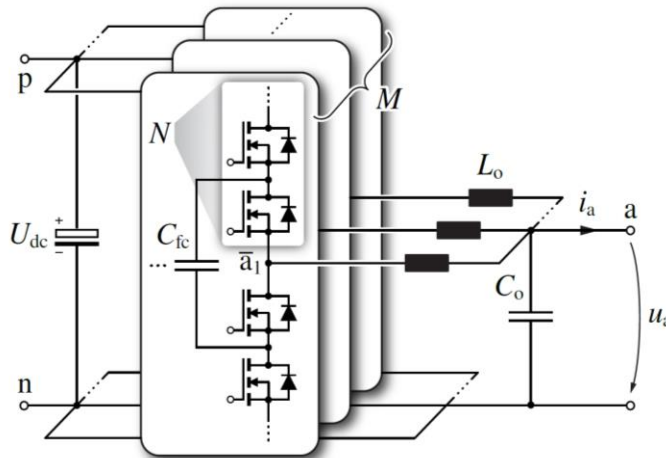


- **200V Si → 200V GaN Technology Results in 99.5% Efficiency**

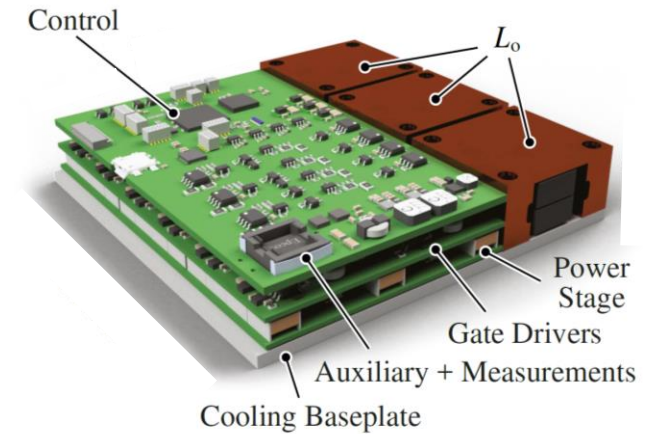
# 4.8MHz GaN Half-Bridge Module



- *Combination of Series & Parallel Interleaving*
- *600V GaN Power Semiconductors,  $f_{sw} = 800kHz$*
- *Volume of  $\approx 180cm^3$  (incl. Control etc.)*
- *H<sub>2</sub>O Cooling Through Baseplate*



**★ 820 W/in<sup>3</sup>**

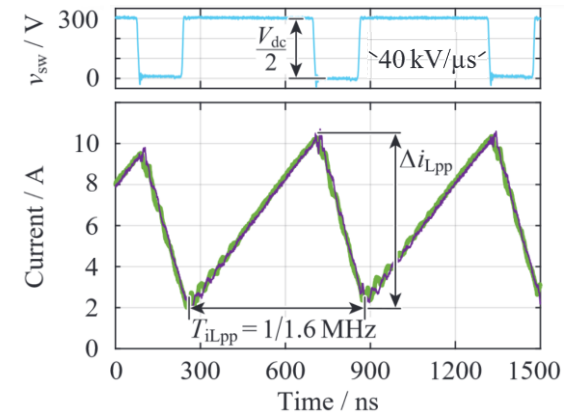
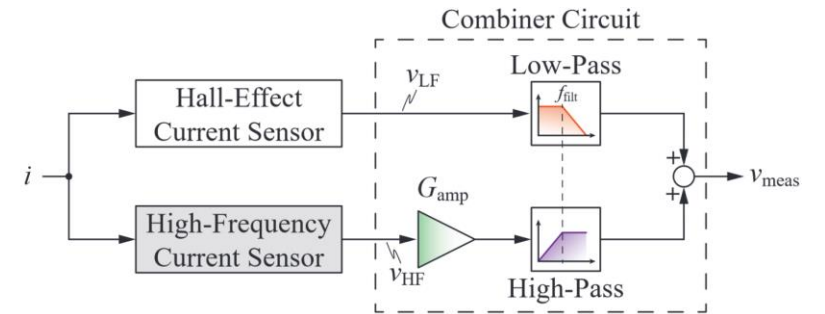
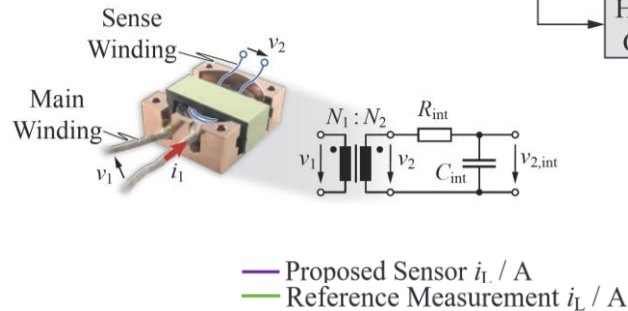
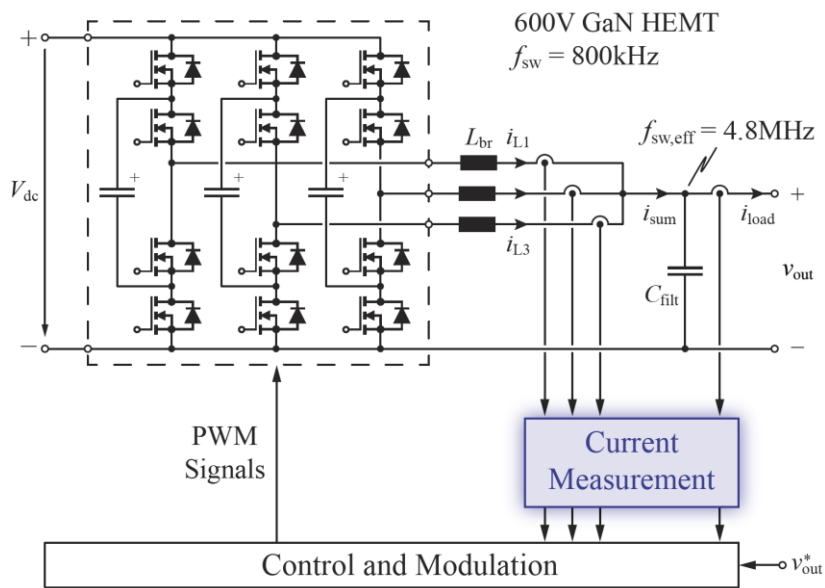


- *Operation @  $f_{out}=100kHz / f_{s,eff} = 4.8MHz, 10kW, U_{dc}=800V$*



# Remark High-BW High-CMRR Current Measurement

- Extension of Commercial Hall Sensor DC...  $f_{Hall} \approx 500\text{kHz} \rightarrow \text{DC} \dots 10\text{MHz}$
- Low-Pass & High-Pass Filter Network Combining HF-Sensor & LF Hall-Sensor



- Hall Sensor Bandwidth  $f_{Hall} = 1.4\text{MHz}$
- Sense Wdg. Integrator Corner Frequency  $f_{int} = 350\text{ Hz}$
- Low/High-Pass Filter Cross-Over Network  $f_{filter} = 15\text{kHz}$

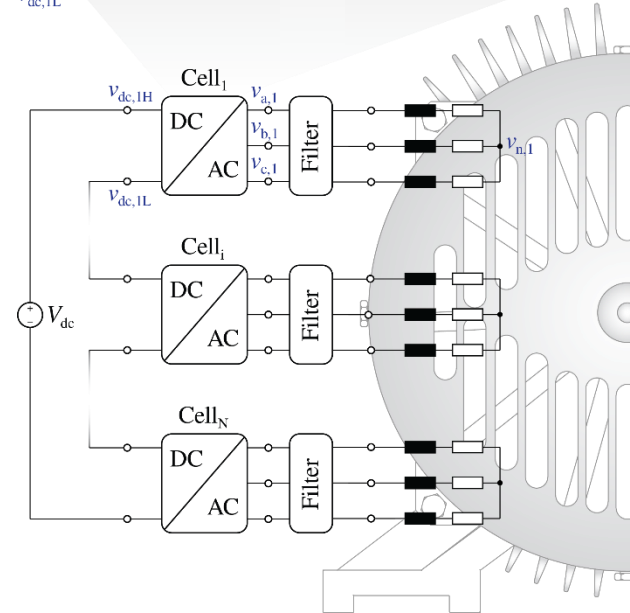
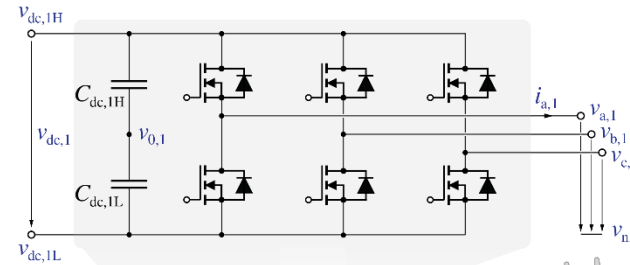
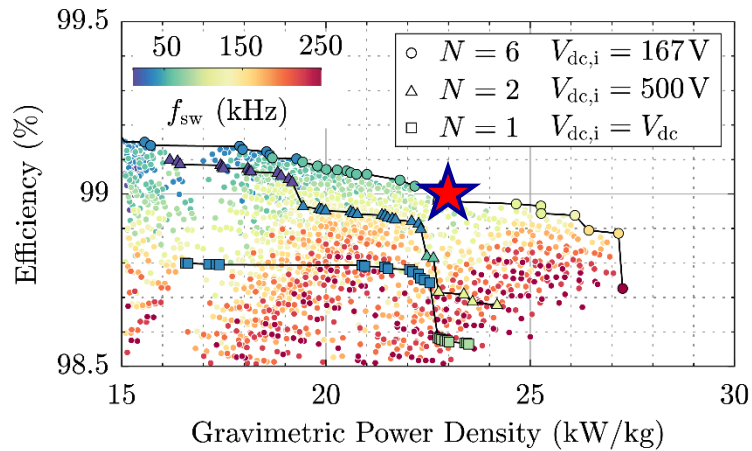
— *Motor-Integrated  
Inverter Systems* —



# Stacked-Multi-Cell (SMC) Inverter

- **Fault-Tolerant VSD**
- **Low-Voltage Inverter Modules**
- **Very-High Efficiency / Power Density**
- **Autom. Manufacturing of Inverter Stage**

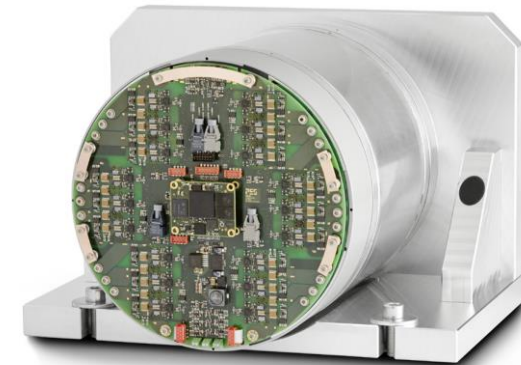
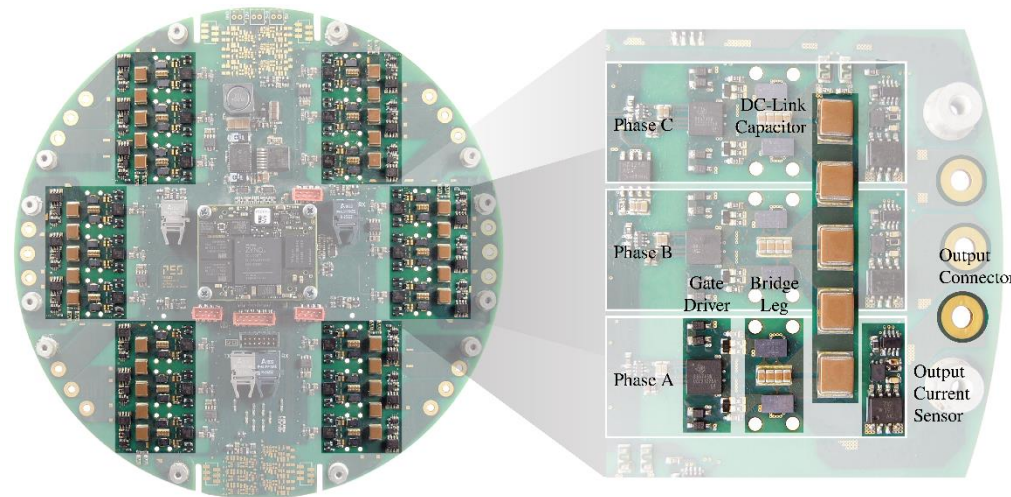
- **Rated Power** 45kW /  $f_{out} = 2\text{kHz}$
- **DC-Link Voltage** 1 kV



- **Smart Motor / Plug & Play | Connected / Intelligent VSD 4.0**

# Motor-Integrated SMC-Inverter

- **Rated Power** 9kW @ 3700rpm
- **DC-Link Voltage** 650V...720V
- **3- $\Phi$  Power Cells** 5+1
- **Outer Diameter** 220mm

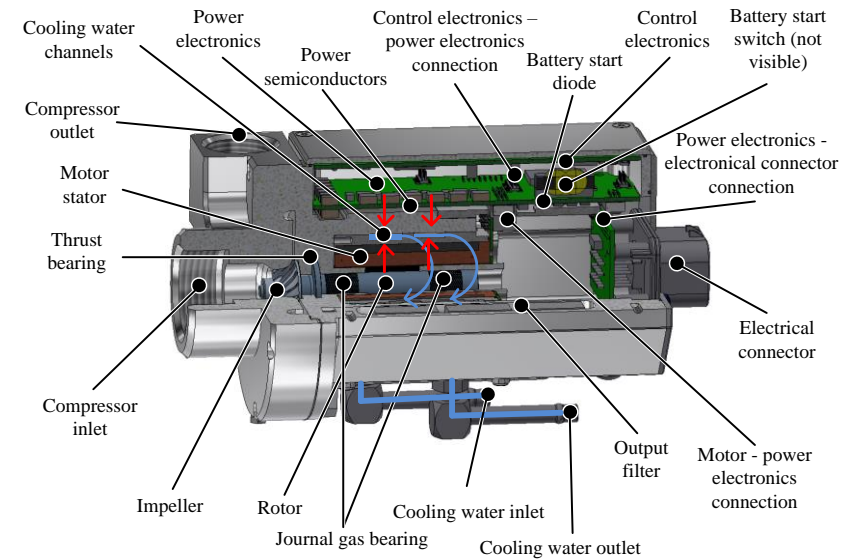
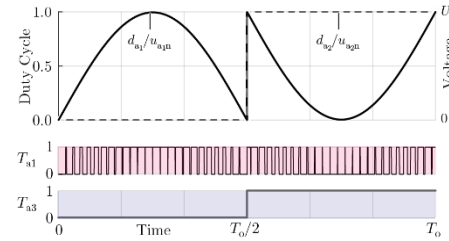
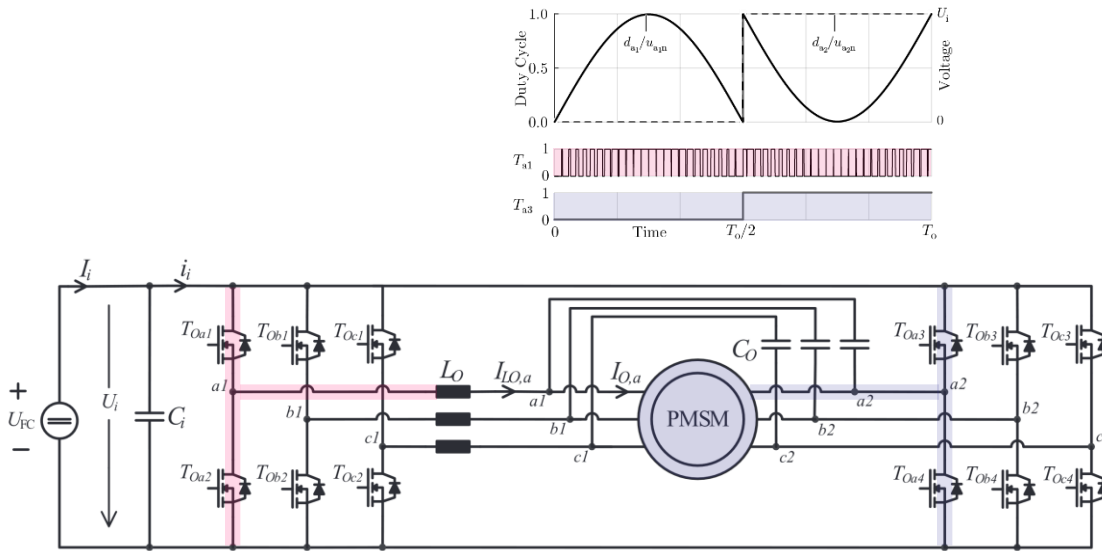


- Axial Stator Mount
- 200V GaN e-FETs
- Low-Capacitance DC-Links
- 45mm x 58mm / Cell

- **Main Challenge** — Thermal Coupling / Decoupling of Motor & Inverter

# Compressor-Integrated DB GaN-Inverter

- *E-Mobility 5...15kW Fuel Cell Pressurized Air Supply*
- *1kW Rated Power,  $f_{sw}=300kHz$  |  $n=280'000rpm$  /  $f_{out}=4.6kHz$*
- *Low EMI / Low Cabling Effort*

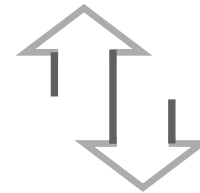


- *Integration → 2x System Power Density | 97% → 98.5% Inverter Efficiency*



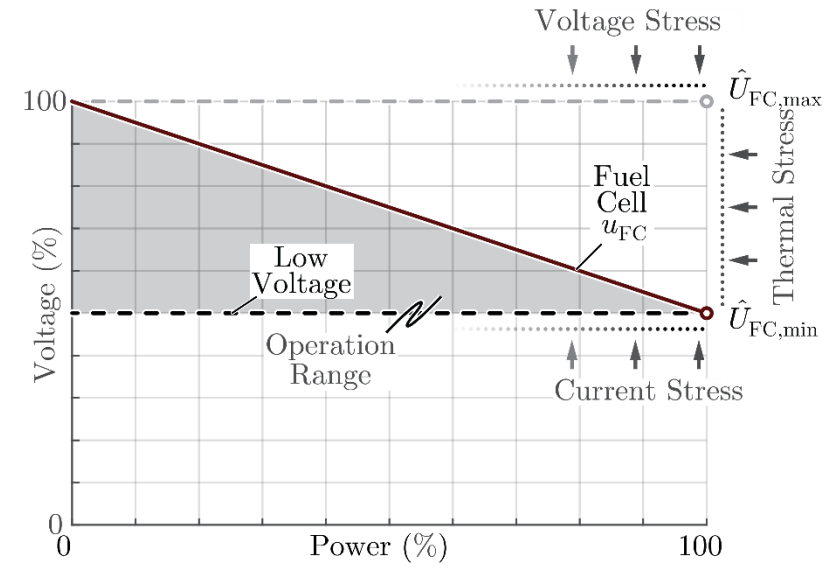
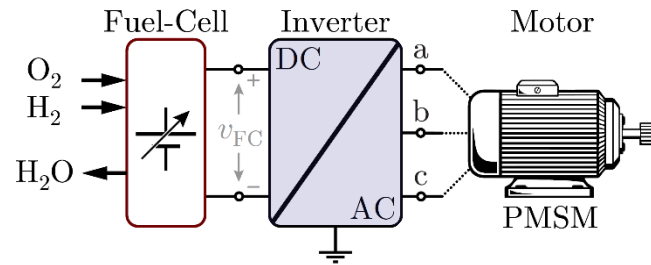
Source: [www.clipart-library.com](http://www.clipart-library.com)

***Buck-Boost  
Inverter***



# Motivation

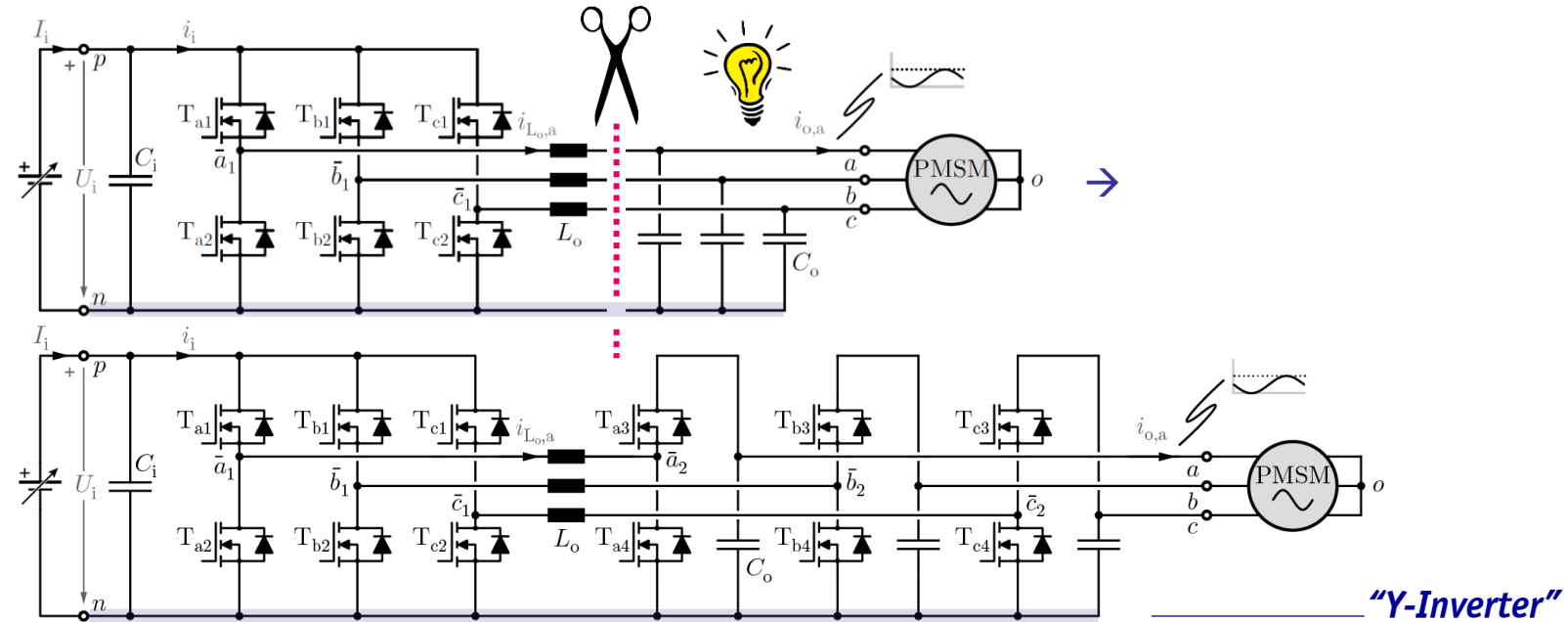
- **General / Wide Applicability**
  - **Adaption to Load-Dependent Battery | Fuel Cell Supply Voltage**
  - **VSDs → Wide Output Voltage / Speed Range**



- **No Additional Converter for Voltage Adaption → Single-Stage Energy Conversion**

# Example — Buck-Boost 3- $\Phi$ Inverter

- Generation of *AC-Voltages Using Unipolar Bridge-Legs*

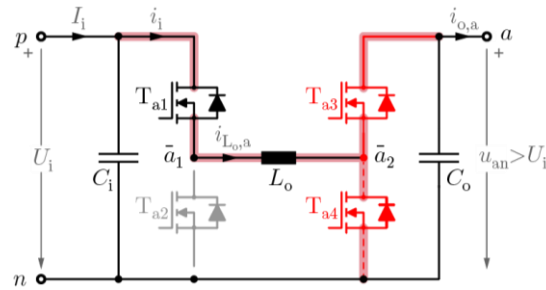


- *Switch-Mode Operation of Buck OR Boost Stage* → *Single-Stage Energy Conversion (!)*
- *3- $\Phi$  Continuous Sinusoidal Output / Low EMI* → *No Shielded Cables / No Motor Insul. Stress*

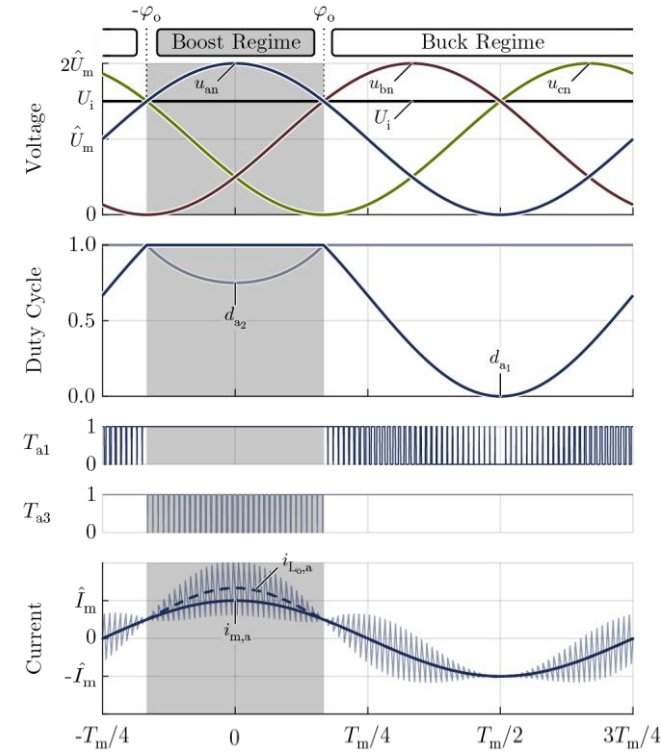
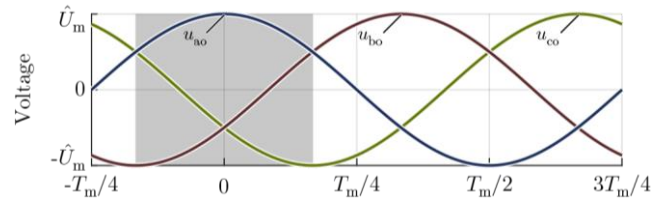


# Boost-Operation $u_{an} > U_i$

## Phase-Module



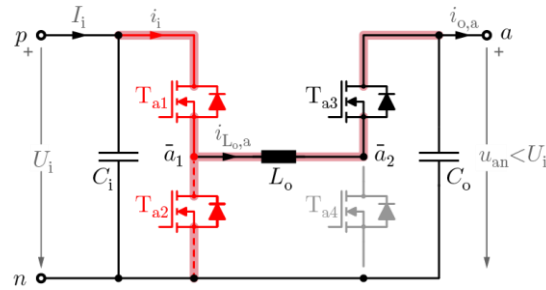
## Motor Phase Voltages



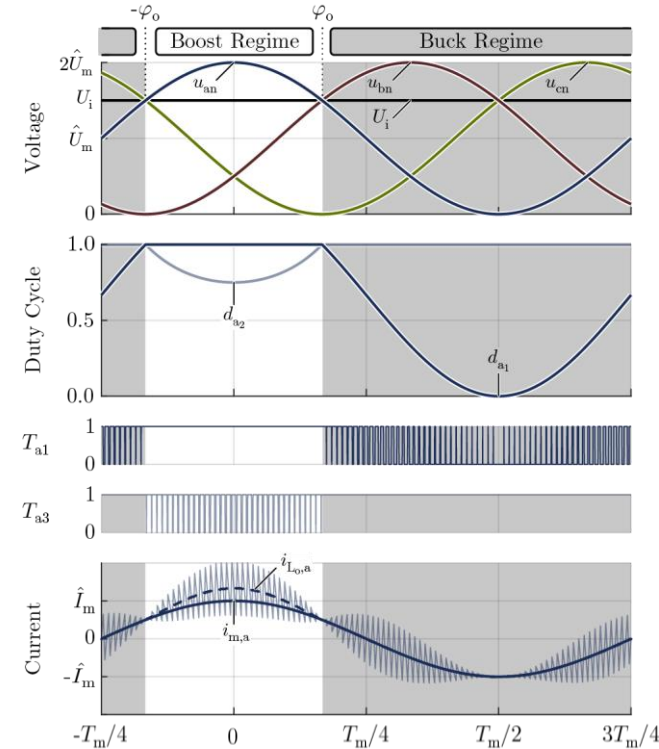
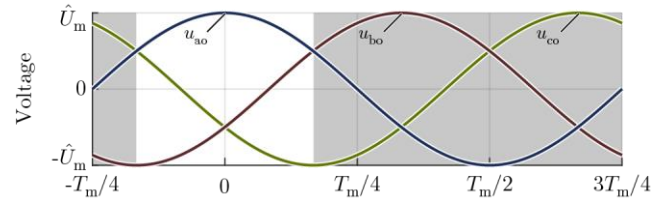
- **Current-Source-Type Operation**
- **Clamping of Buck-Bridge-Leg High-Side Switch** → **Quasi Single-Stage Energy Conversion**

# Buck-Operation $u_{an} < U_i$

## Phase-Module



## Motor Phase Voltages



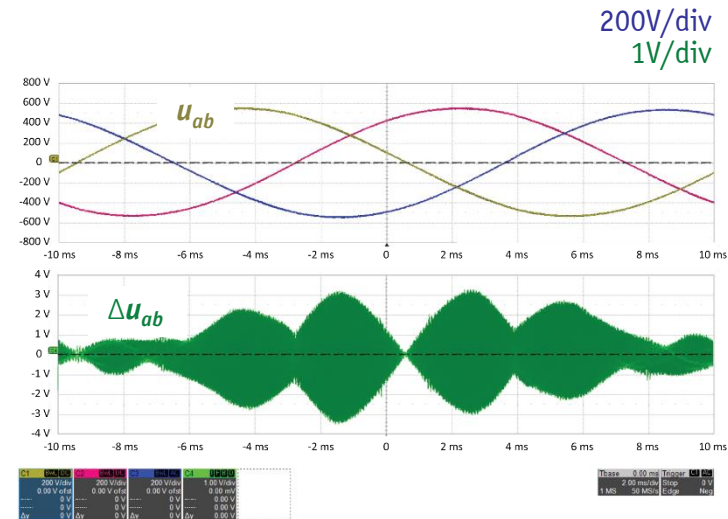
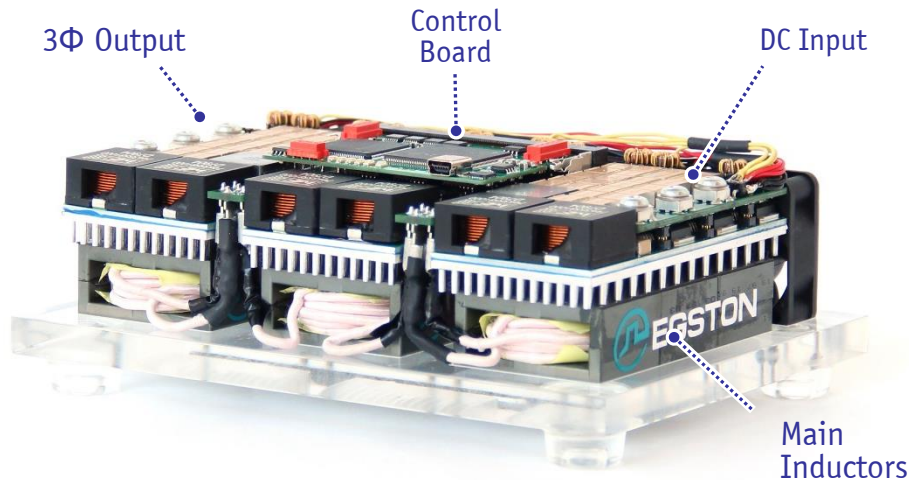
- Voltage-Source-Type Operation
- Clamping of Boost-Bridge-Leg High-Side Switch → Quasi Single-Stage Energy Conversion



# 3- $\Phi$ Buck-Boost Inverter Lighthouse Project

- Rated Power **10 kVA**
- DC Input Range **400...750V<sub>DC</sub>**
- AC Output **0...230V<sub>rms</sub> (Phase)**  
**0...500Hz**
- 1200V SiC MOSFETs **25m $\Omega$  | 100kHz**

★ **245 W/in<sup>3</sup>**  
**98.3%**



- **No Shielded Motor Cables / Cond. & Radiated EMI Compliant to IEC 61800-3**

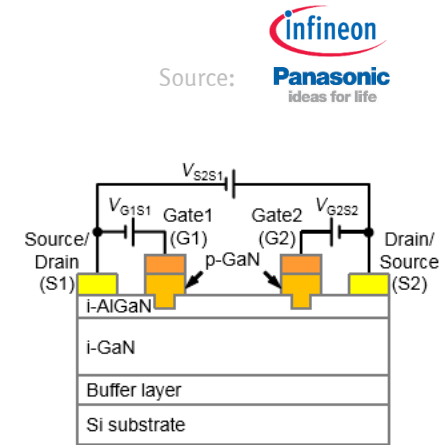
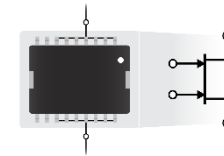
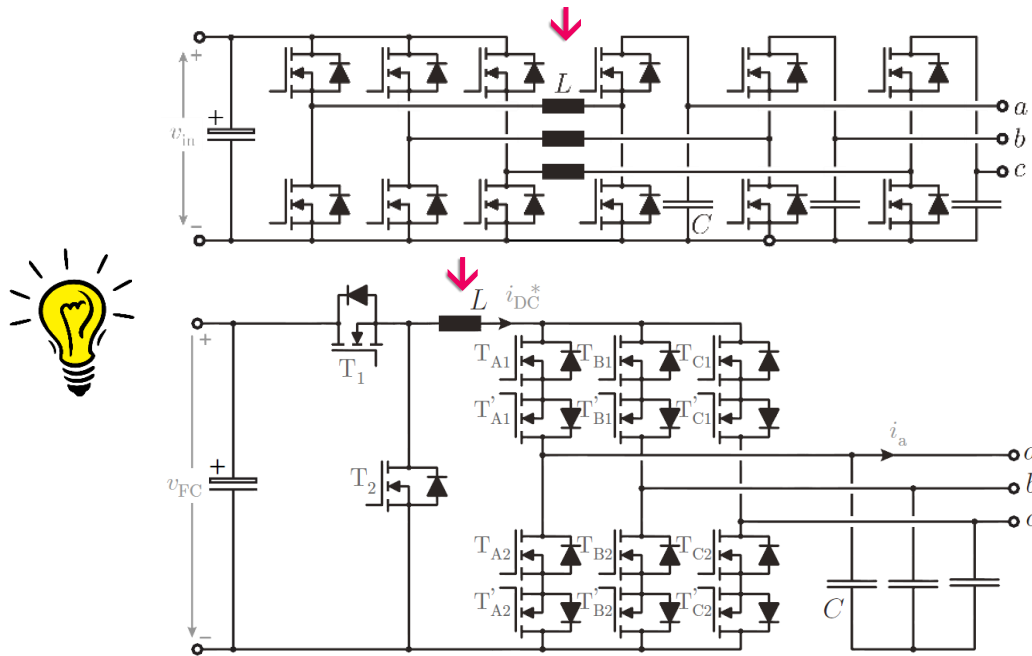


Source: [www.clipart-library.com](http://www.clipart-library.com)

## ***I-DC Link Inverters***

# 3- $\Phi$ Current DC-Link Topologies

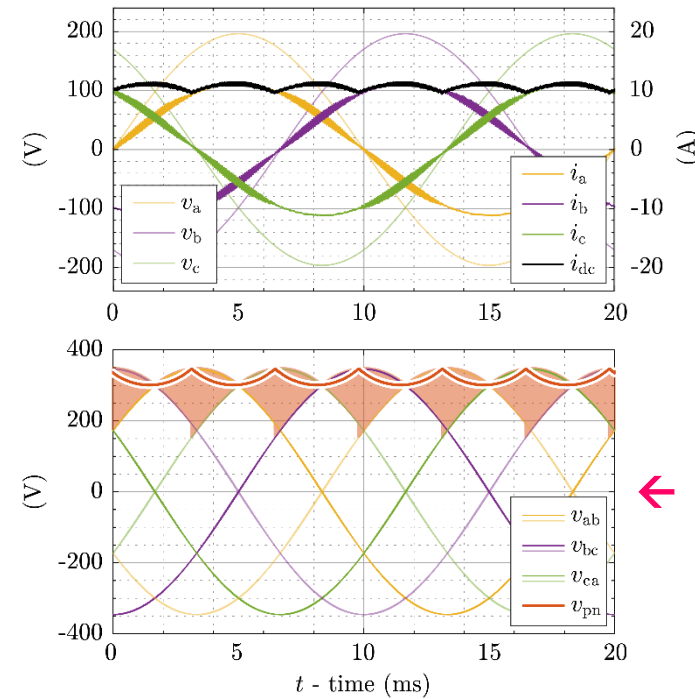
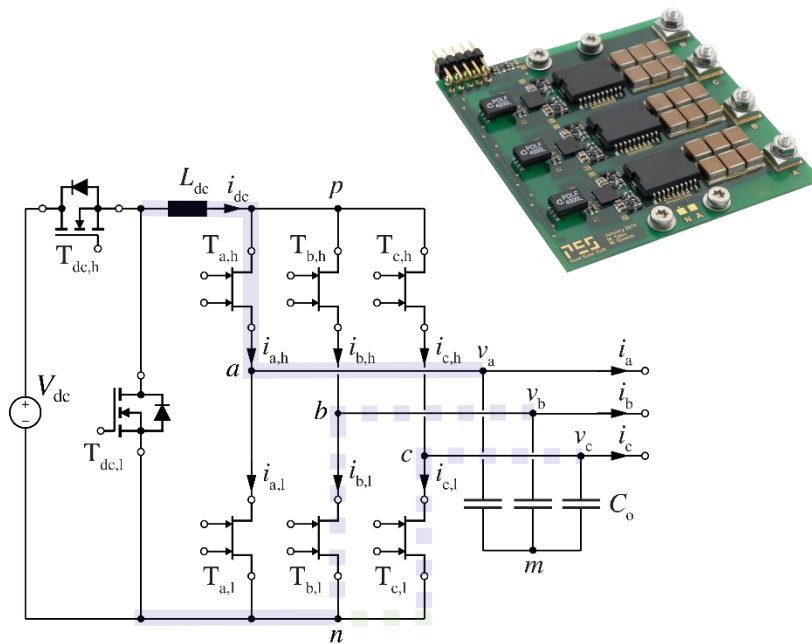
- 3- $\Phi$  Buck-Boost Inverter  $\rightarrow$  Phase Modules w/ Buck-Stage | Current Link | Boost-Stage
- 3- $\Phi$  Current DC-Link Inv.  $\rightarrow$  Buck-Stage V-I-Converter | Current DC-Link DC/AC-Stage



$\rightarrow$  Single Inductive Component & Utilization of Monolithic Bidirectional GaN Switches

# 3- $\Phi$ -Integrated Buck-Boost CSI

- **“Synergetic” Control of Buck-Stage & CSI Stage**
- **6-Pulse-Shaping of DC Current by Buck-Stage  $\rightarrow$  Allows Clamping of a CSI-Phase**

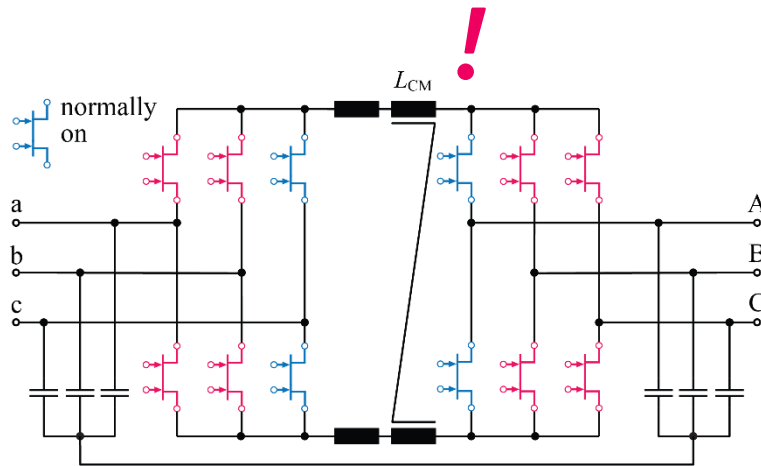


- **Switching of Only 2 of 3 Phase Legs  $\rightarrow$  Reduction of Sw. Losses by  $\approx$  86% (!)**

## 3- $\Phi$ AC/AC Converter Topologies

### ■ Current DC-Link Topology

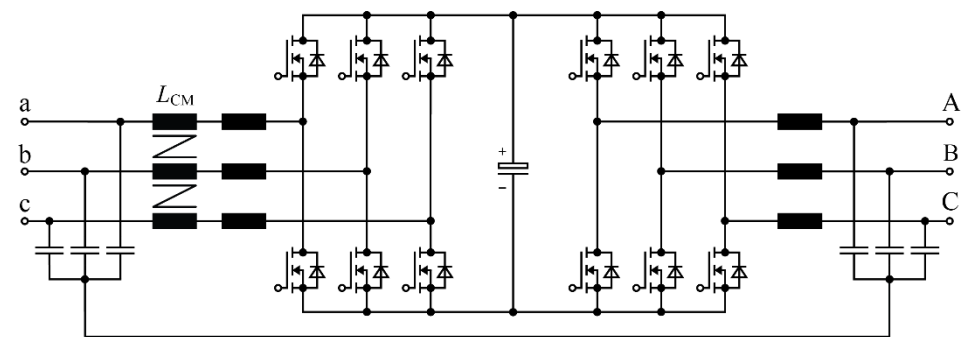
- Application of *M-BDSs*
- Complex 4-Step Commutation
- Low Filter Volume



- Challenging Overvoltage Protection
- Limited Control Dynamics

### ■ Voltage DC-Link Topology

- Standard Bridge-Legs
- Low-Complexity Commutation
- Defined Semiconductor Voltage Stress
- Facilitates DC-Link Energy Storage

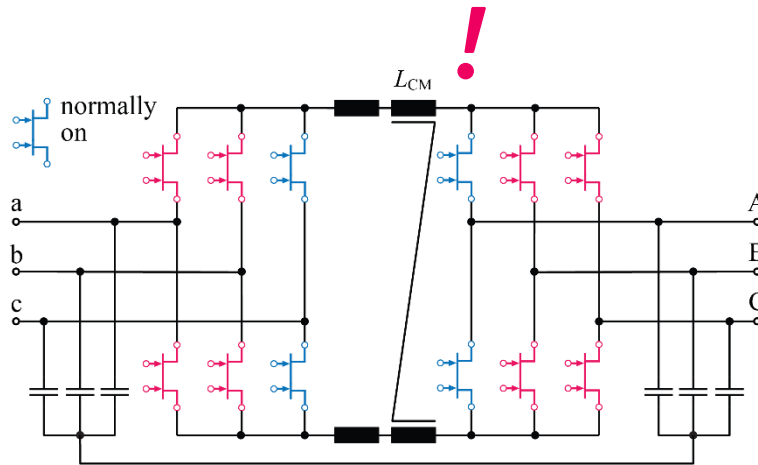


- High Input / Output Filter Volume

# 3- $\Phi$ AC/AC Converter Topologies

## ■ Current DC-Link Topology

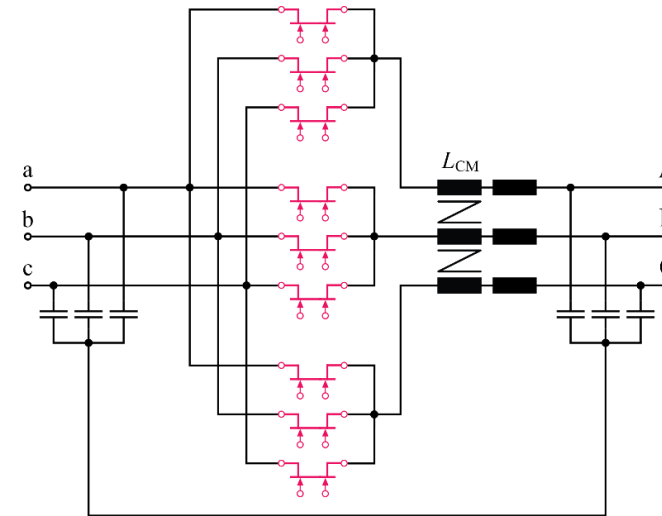
- Application of M-BDSs | 12 Switches
- 4-Step Commutation
- Buck-Boost Functionality
- Low Filter Volume



- Challenging Overvoltage Protection

## ■ Direct Matrix Converter

- Application of M-BDSs | 9 Switches
- 4-Step Commutation
- Complex Space Vector Modulation
- Limited to Buck-Operation (!)

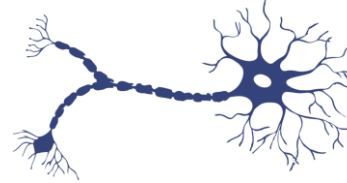


- Challenging Overvoltage Protection



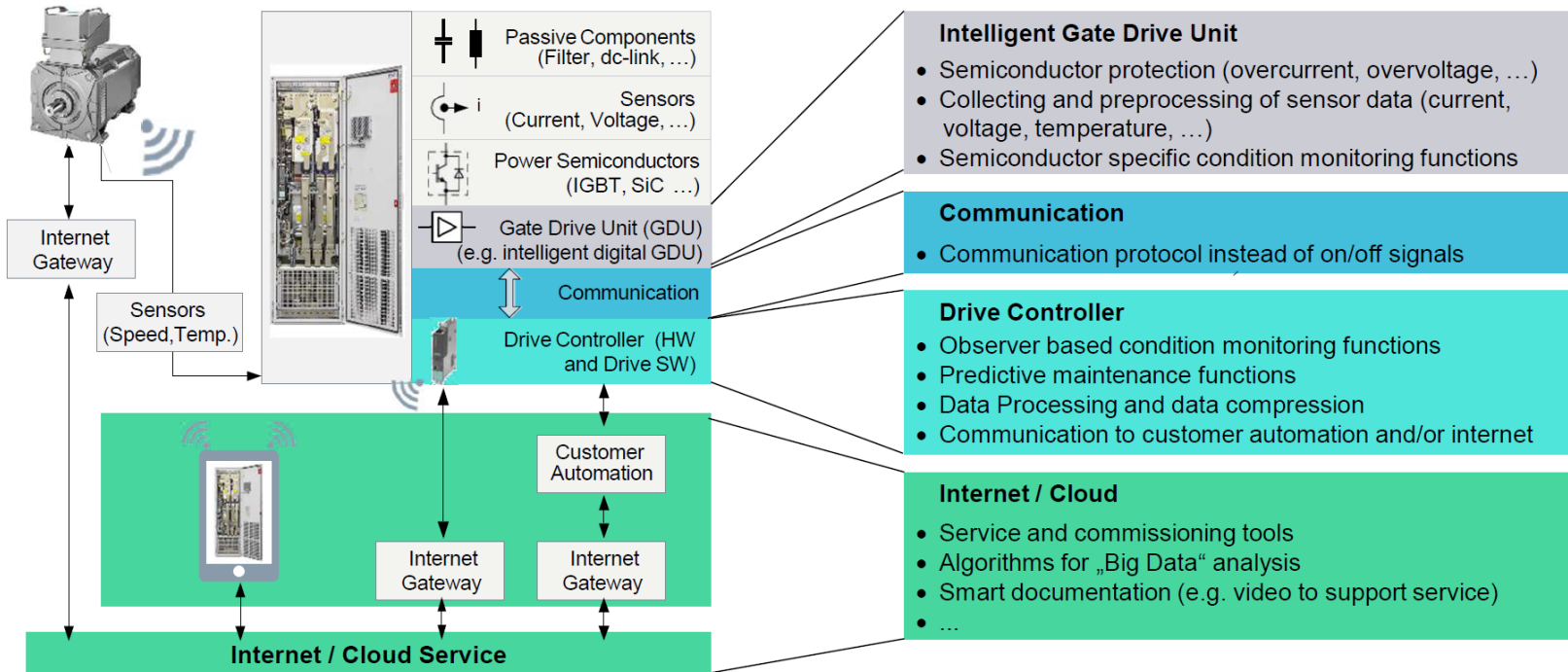
— Conclusion —

# Smart Inverter Concept



- Utilize High Computing Power & Network Effects in the Cloud → **Cognitive Power Electronics**

Source: Dr. R. Sommer  
**SIEMENS**



- Component Level | Converter Level | System Level | Application Level**

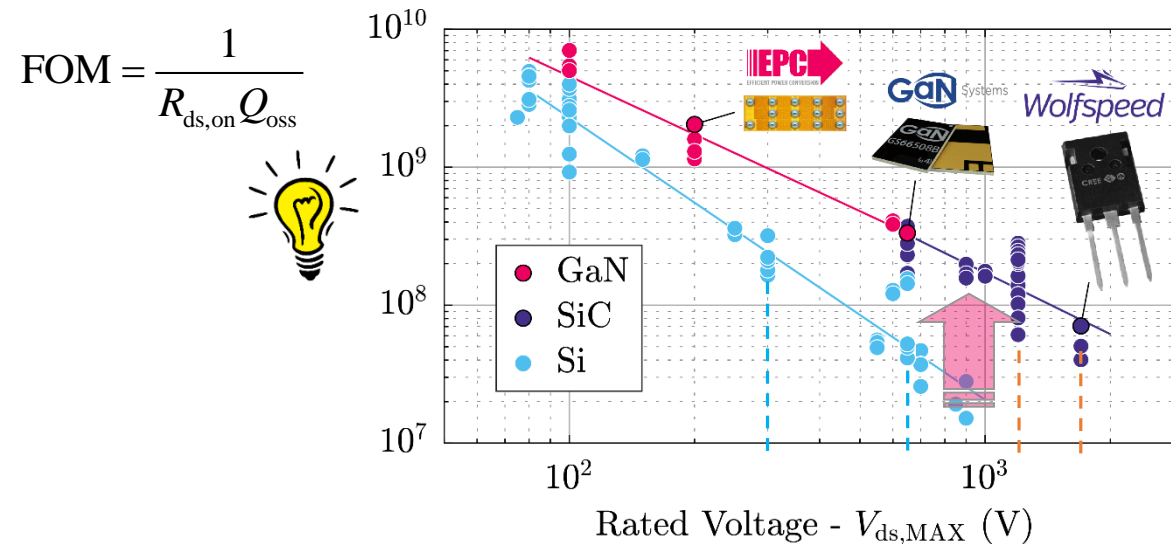
**Thank you!**





## SiC/GaN Figure-of-Merit

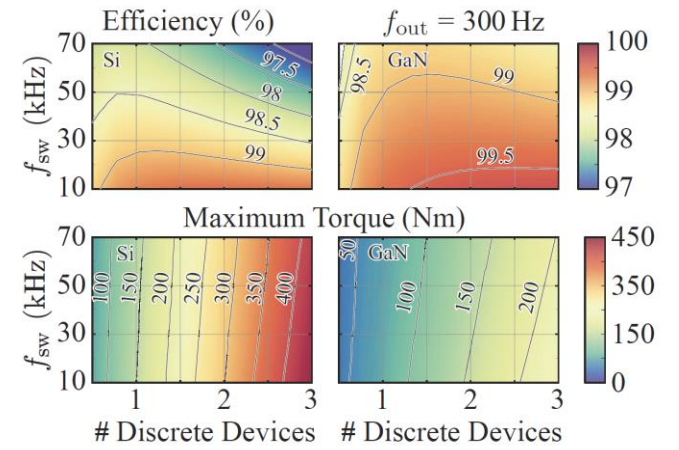
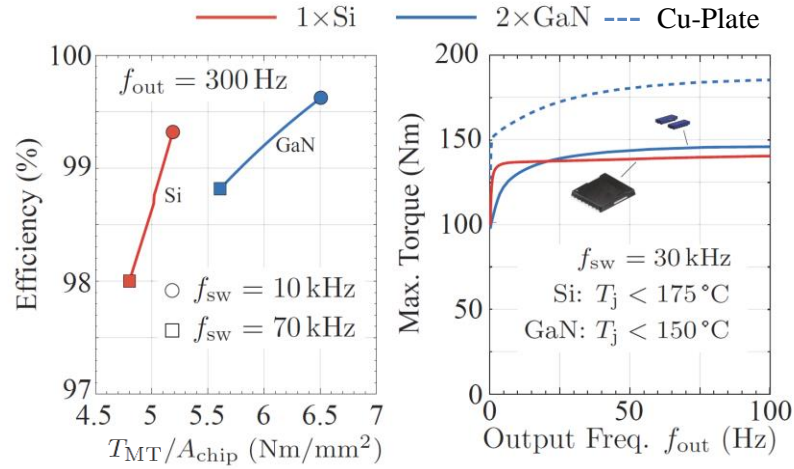
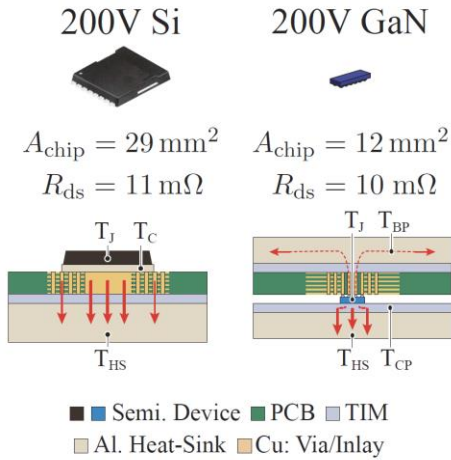
- *Figure-of-Merit (FOM) Quantifies Conduction & Switching Properties*
- *FOM Identifies Max. Achievable Efficiency @ Given Sw. Frequ.*



- *Advantage of Multi-Level over 2-Level Converter Topologies*

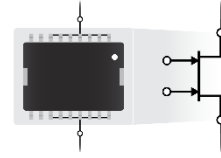
# Remark GaN Overload Capability

- Highly Dynamic Robotics VSDs → 3x ... 5x Rated Torque for Seconds
- Smaller Chip Area → Lower Thermal Time Constant of GaN HEMTs
- Trade-Off Between Overload Rating & Rated Power Efficiency

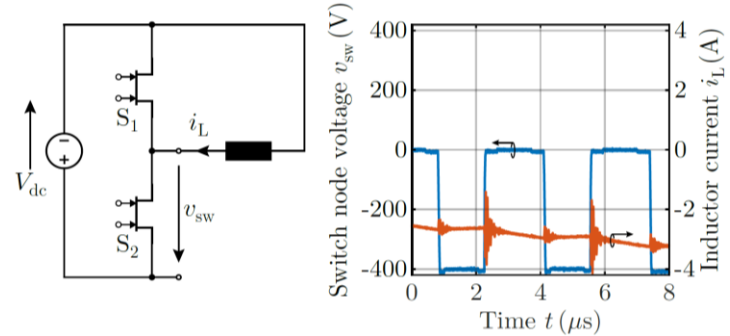
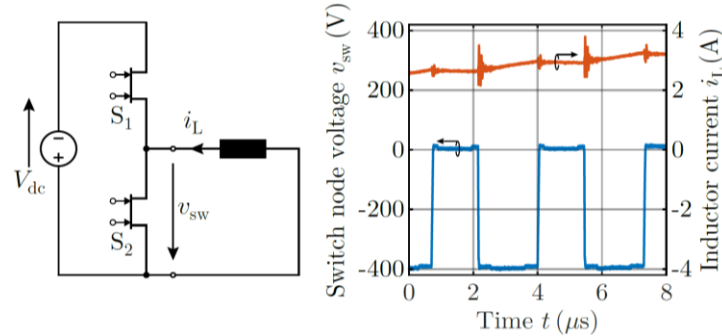
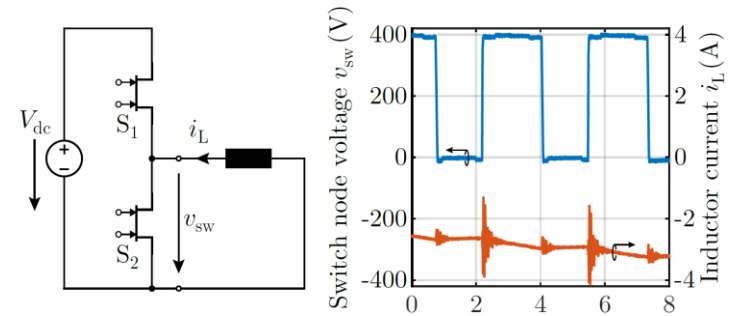
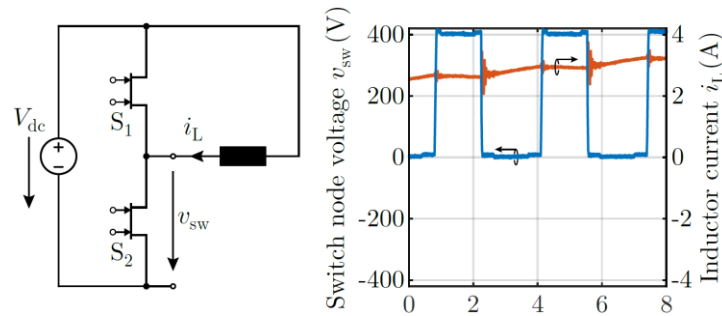
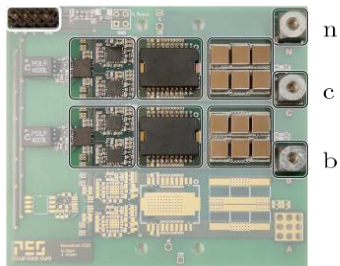
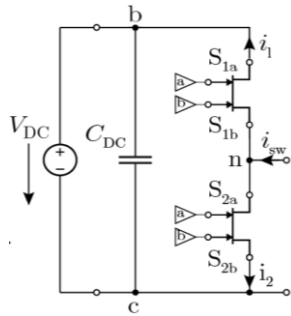


- 200V GaN vs. Si (Multi-Level Inverter) Comparison

# 600V GaN Monolithic Bidir. Switch



- Power America Project — Based on Infineon’s CoolGaN™ HEMT Technology ( $R_{DS(on)} = 70m\Omega$ ) 
- Dual-Gate Device / Controllability of Both Current Directions
- Bipolar Voltage Blocking Capability | Normally On or Off

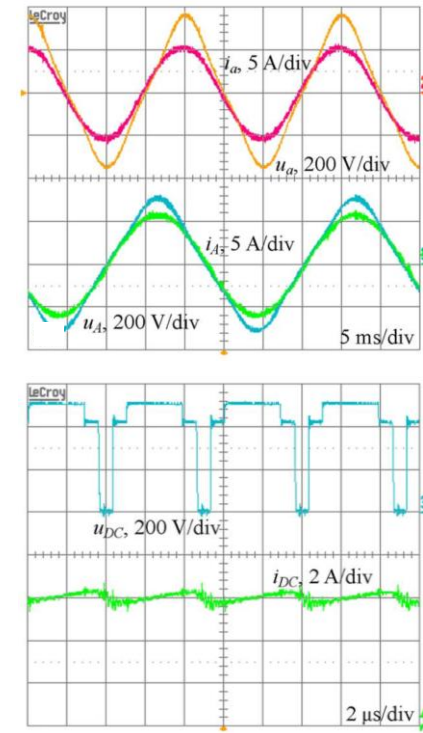
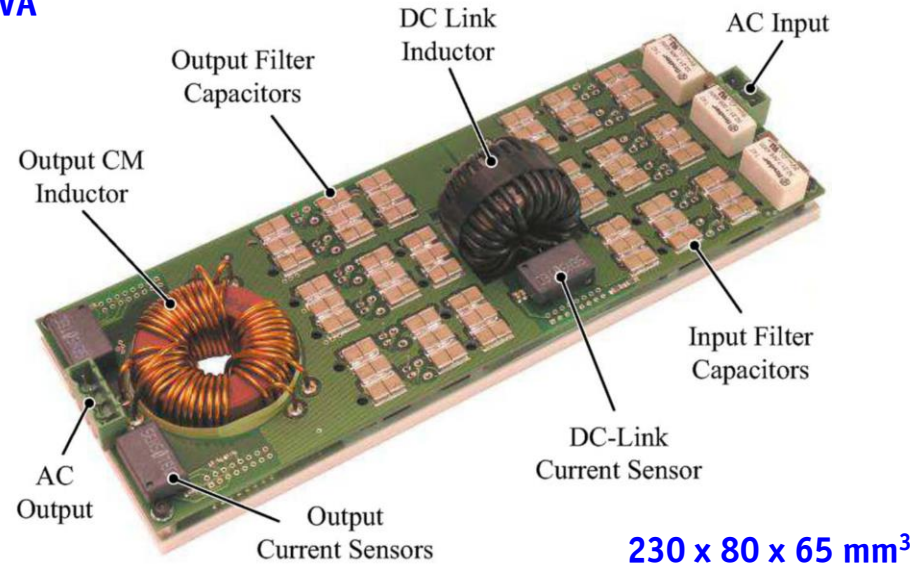


- Analysis of 4-Quadrant Operation of  $R_{DS(on)} = 140m\Omega$  Sample @  $\pm 400V$

## 200kHz SiC Current DC-Link AC/AC Converter

- *7kHz DC-Link Current Control Bandwidth*
- *PCB-Stack Construction — Power | Gate-Drive | Control Board*
- *Coldplate Cooling*

Input **400V<sub>rms</sub> Line-to-Line**  
 Output **0...300Hz**  
 Rated Power **2.5 kVA**  
**2.4 kVA / dm<sup>3</sup>**  
**(40 W/in<sup>3</sup>)**



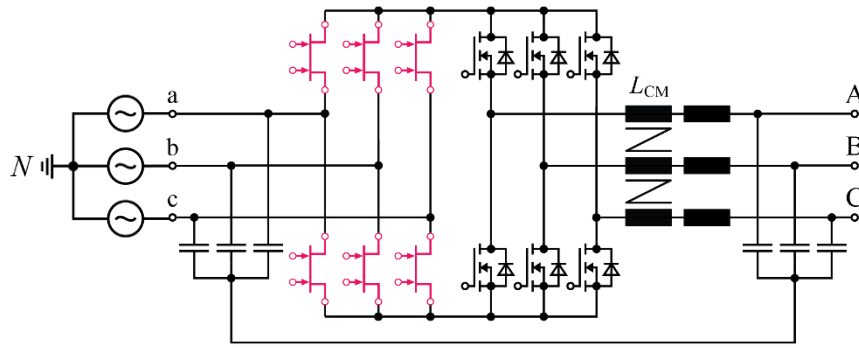
- *Low Volume Toroidal Powder Core DC-Link Inductor (320uH)*



# Remark 3- $\Phi$ AC/AC Matrix Converter

## Indirect Matrix Converter (IMC)

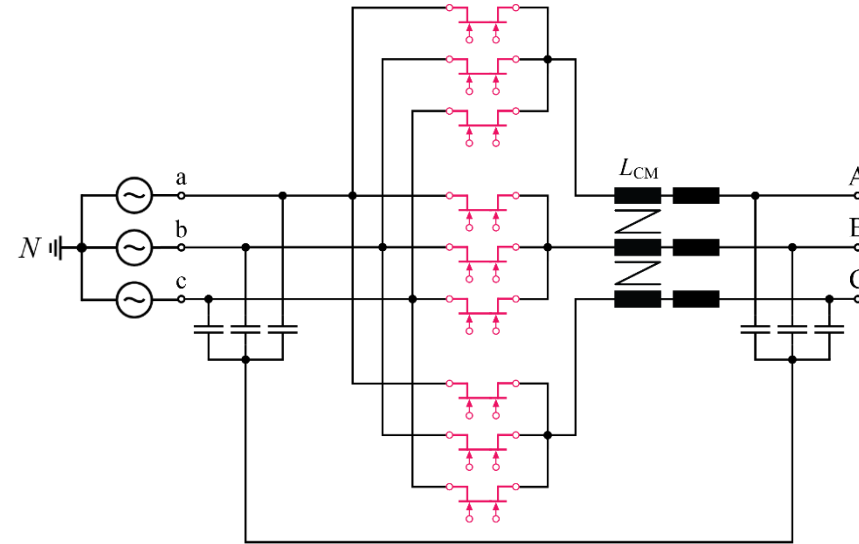
- CSI GaN M-BDS AC/DC Front-End
- ZCS Commutation of CSI Stage @  $i_{DC}=0$
- No 4-Step Commutation



- Higher # of Switches Compared to CMC
- Lower Cond. Losses @ Low Output Voltage
- Thermally Critical @  $f_{out} \rightarrow 0$

## Direct Matrix Converter (CMC)

- 4-Step Commutation
- Exclusive Use of GaN M-BDSs



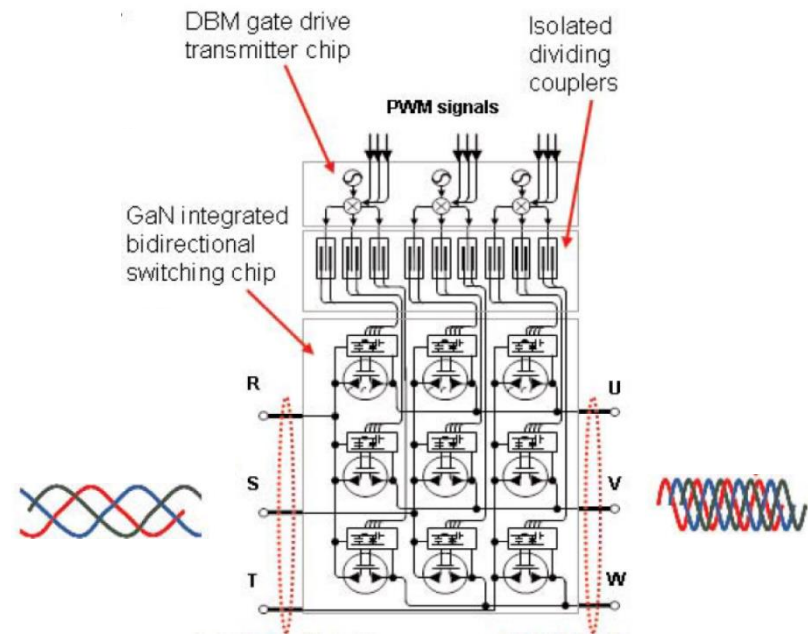
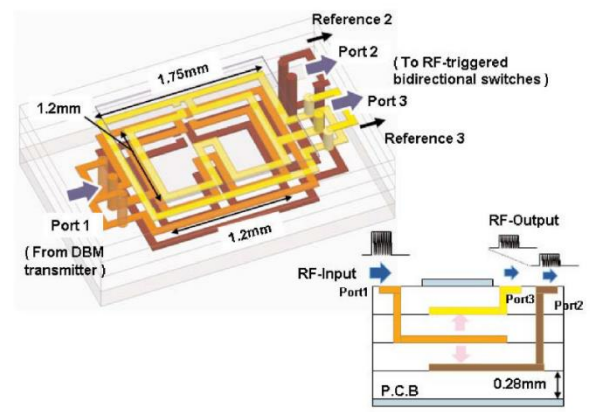
- Thermally Critical @  $f_{out} \approx f_{in}$

# Monolithic 3D-Integration

Source: **Panasonic** ISSCC 2014

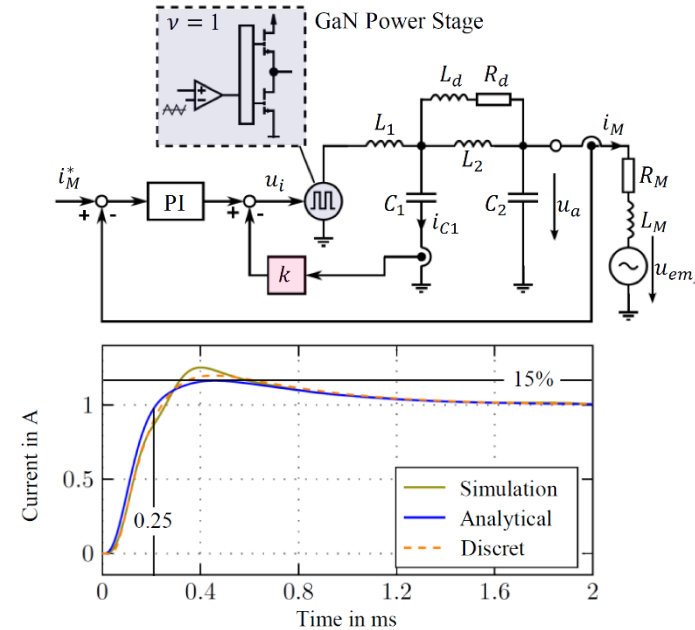
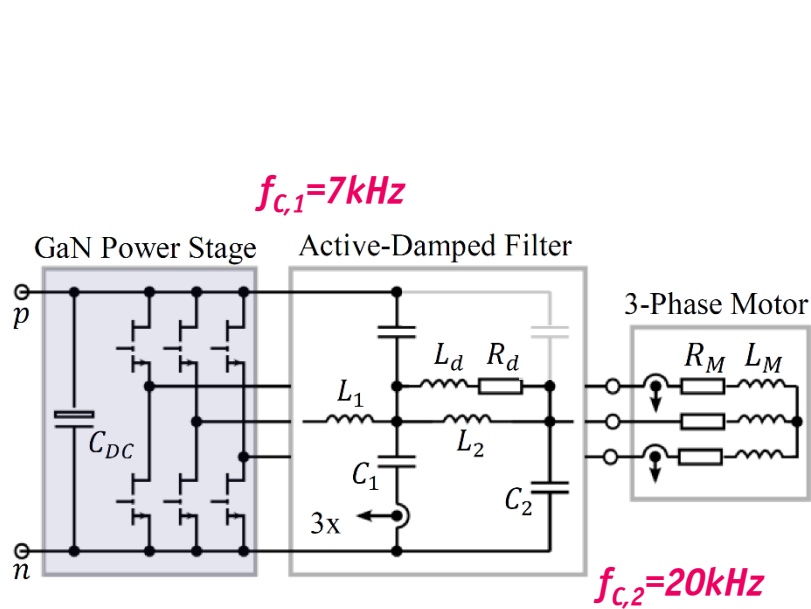
- **GaN 3x3 Matrix Converter Chipset with Drive-By-Microwave (DBM) Technology**
  - **9 Dual-Gate GaN AC-Switches**
  - **DBM Gate Drive Transmitter Chip & Isolating Couplers**
  - **Ultra Compact → 25 x 18 mm<sup>2</sup> (600V, 10A – 5kW Motor)**

5.0GHz Isolated (5kVDC) Dividing Coupler



## 2-Stage Full-Sinewave Output Filter

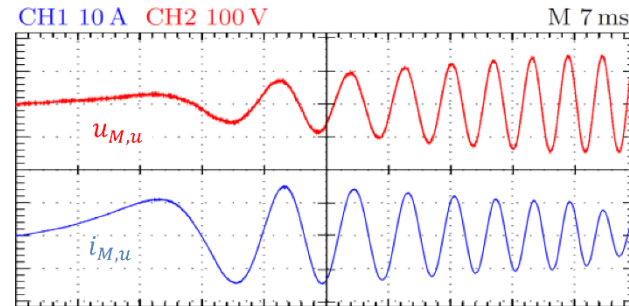
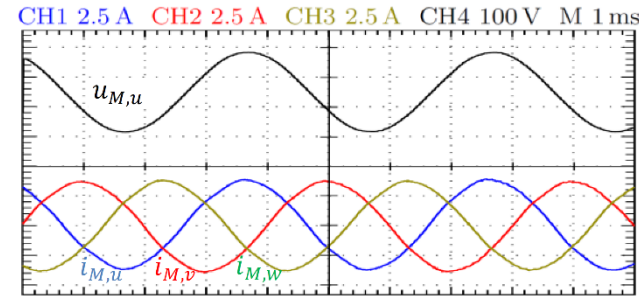
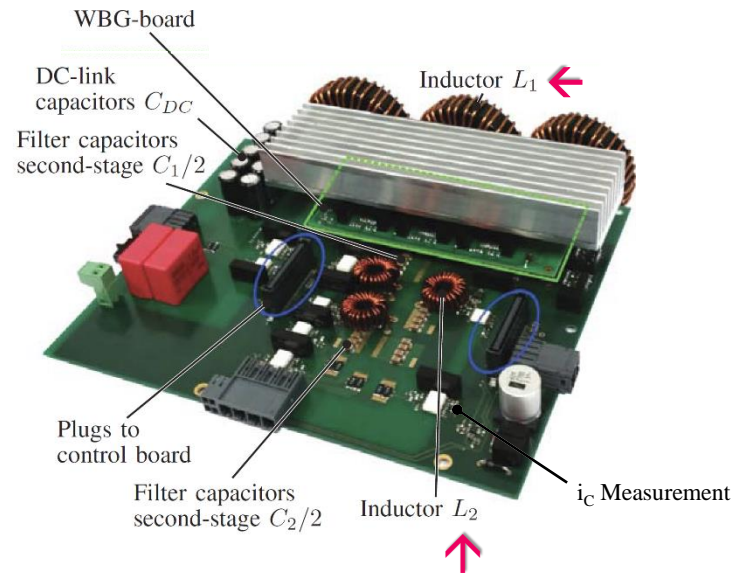
- 2kW / 400V DC-Link 3- $\Phi$  650V GaN Inverter ( $I_M=5A$ ),  $f_{out,max} = 500Hz$
- Sinewave Output & IEC/EN 55011 Class-A
- Sw. Frequency  $f_s=100kHz$



- Soft Saturation Toroidal Iron Powder Cores
- Active & Passive Damping of the Filter Stages

## 2-Stage Full-Sinewave Output Filter

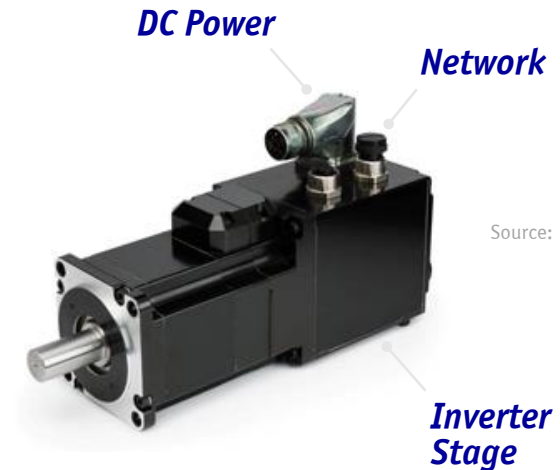
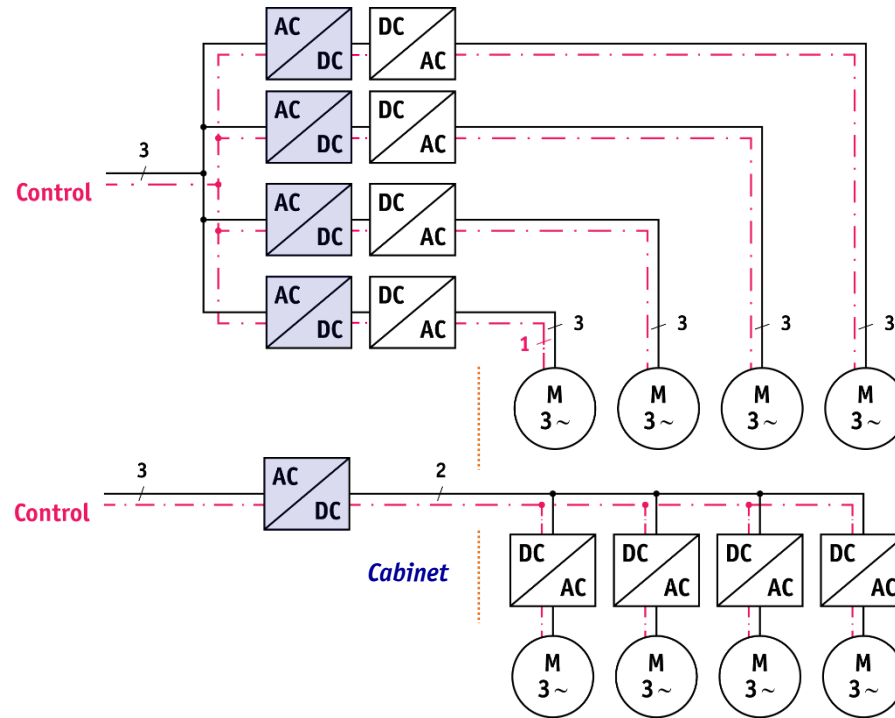
- **Exp. Verification** — 650V E-Mode GaN Systems Transistors (50mΩ)
- **Sw. Frequency**  $f_s = 100\text{kHz}$ , Efficiency  $\approx 98\%$
- **200mm x 250mm**



- **Stationary Motor Phase Curr. /Voltage @ 2.5Nm &  $f_{out} = 250\text{Hz}$**
- **Speed Increase from Standstill to  $n = 3000\text{rpm}$  in 60ms**

# Multi-Axis Drive Systems

- **Common DC-Bus** — **Single AC/DC Converter / Smaller Cabinet**
- **Motor Integration of DC/AC Stage** — **Massive Saving in Cabling Effort / Simplified Installation**

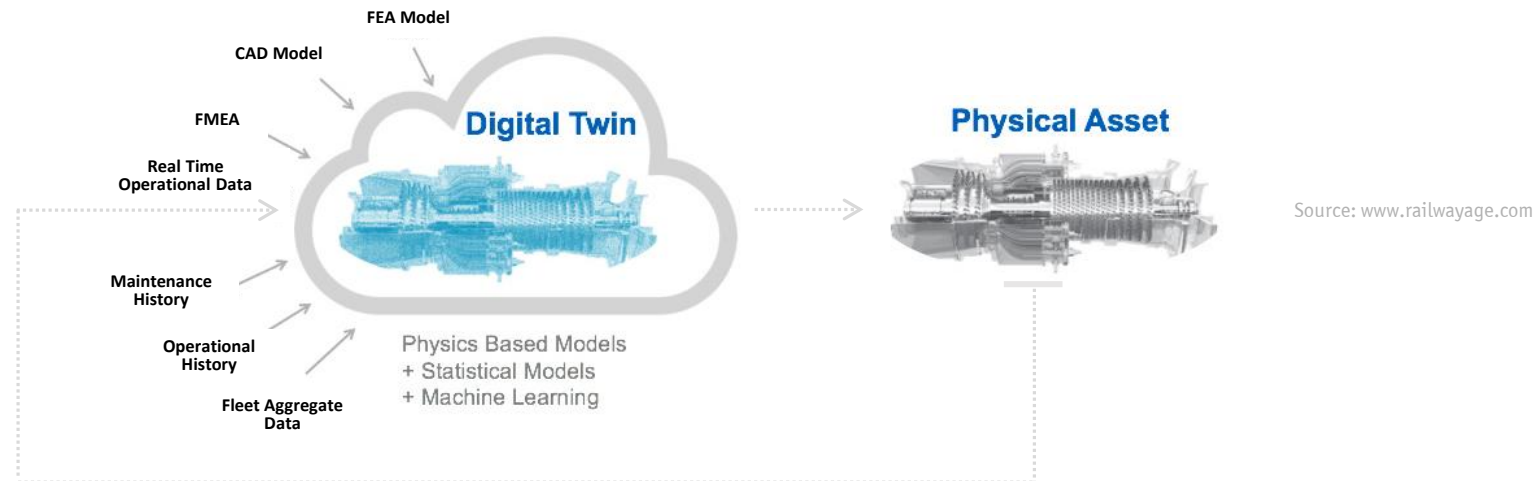


Source: **YASKAWA**

- **Facilitates DC-Bus Energy Buffer**
- **Direct Energy Exchange @ DC-Bus / Higher Efficiency / Unidir. Front-End**

## IIoT in Power Electronics

- **Digital Twin** → **Physics-Based Digital Mirror Image**
- **Digital Thread** → **“Weaving” Real/Physical & Virtual World Together**



- **Requires Proper Interfaces for Models & Automated Design**
- **Model of System's Past/Current/Future State** → **Design Corrections / Prev. Maintenance etc.**

**End** 